

Passivation and segmentation developments at LNL

Daniel R. Napoli

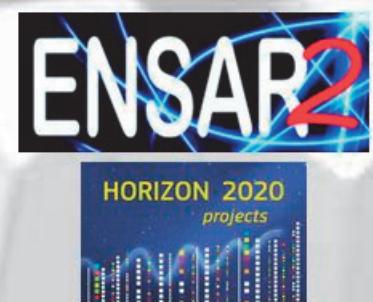
INFN Legnaro, Italy



UNIVERSITÀ
DEGLI STUDI
DI PADOVA



ENSAR2
Work Package 10 - Joint Research Activity 2
Research & Development on
Position-Sensitive Germanium Detectors
CSIC – CNRS – GSI – IKP – INFN – Univ. of Liverpool





Work Package n. 10 - JRA2 PSeGe

R&D on Position-Sensitive Germanium Detectors for Nuclear Structure and Applications

Task 1: New technologies on passivation and segmentation of HPGe
(Coordination: INFN)

Task 2: R&D on novel Ge-detector geometries for ultimate position resolution and efficiency
(Coordination: GSI)

Task 3: R&D on segmented p-type coaxial detectors
(Coordination: CSIC)

Task 4: Network activity: Demonstration of imaging applications and associated detector technologies
(Coordination: Univ. of Liverpool)

Coordinators: A.Gadea (CSIC, **JRA2 leader**), D.R.Napoli (INFN, **deputy**),
P.Reiter (IKP, **deputy**), J.Gerl (GSI), A.Boston (U.of Liverpool)

Task 1: The aim is to find new passivation methods for solving the instabilities of the intrinsic Ge surfaces in between contacts and segments, which lead to an increase of the leakage current and a reduction of both energy and position resolution.

The interdisciplinary group of the Materials Laboratory of the LNL is studying chemical and physical methods of passivation in HPGe.

Task 3: In position-sensitive detectors for tracking arrays, the most important signals are the ones from the segments. Thus, a development focused on the possibility to use p-type HPGe detectors will greatly benefit present and future detector arrays.

This task proposes a R&D on alternative materials for n- and p-type contacts that could be segmented.

The interdisciplinary group of INFN-LNL is also participating to this task.

Main topics of our current activity at LNL

- To study the effects of the passivation of the intrinsic surface on the HPGe detector characteristics (depletion voltage, resolution, efficiency, dead layer, ...)
- To develop new passivation/protection techniques
- To develop new thinner contacts, which could replace the present ones (especially Li)
- To improve the method of construction and the robustness of the surfaces for costs reduction in both fabrication and maintenance (needed also for applications).

Multidisciplinary Team



INFN-LNL



INFN-LNL and University of Padua:



INFN-LNL and University of Verona

INFN-LNL and University of Trento

INFN-PG and University of Camerino
INFN-PG and University of Perugia

CSIC-IFIC of Valencia

IKP Cologne

CNR-IMM Bologna



D.R. Napoli, W. Raniero

D. De Salvador, G. Maggioni, S. Carturan
E. Napolitani, V. Boldrini, F. Sgarbossa

G. Mariotto

G. Della Mea

N. Pinto
S. Riccetto

A. Gadea, S. Bertoldo

J. Eberth

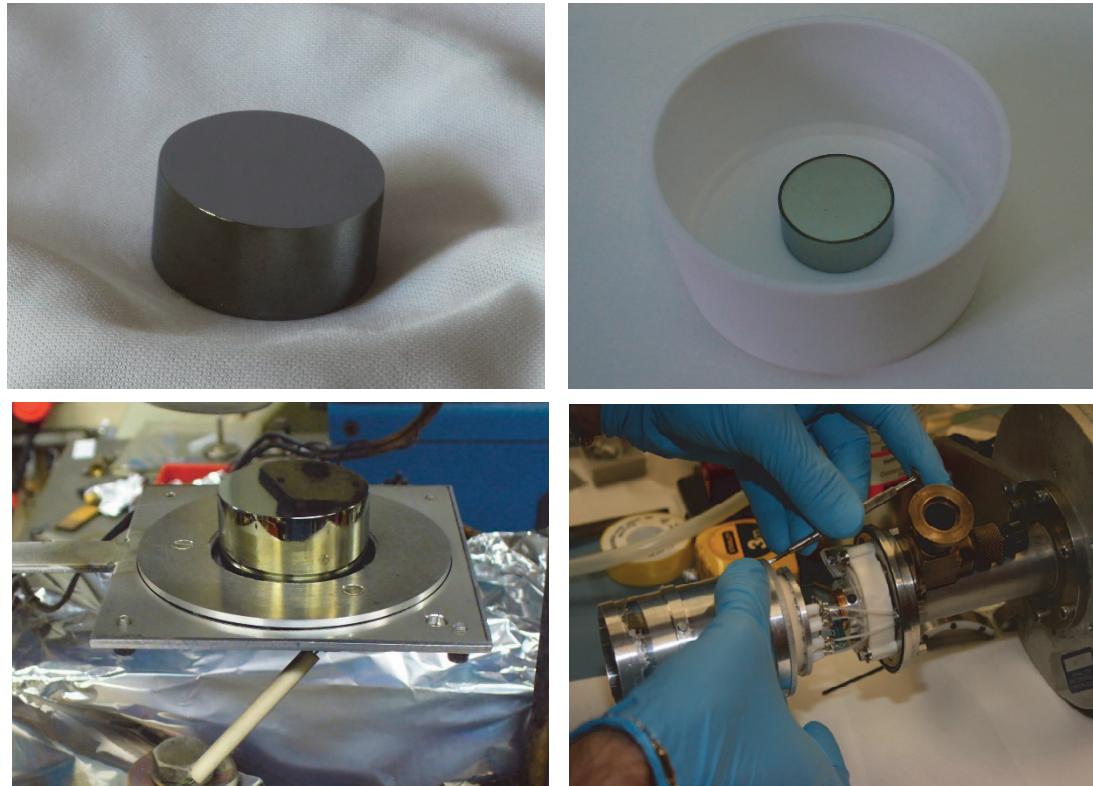
R. Nipoti, F. Mancarella, M. Bellettato



High Purity Ge detectors production

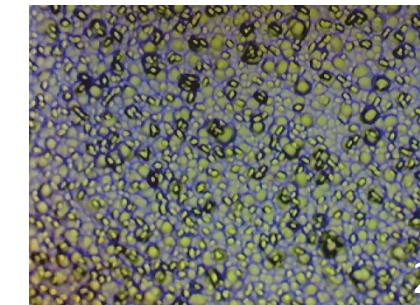
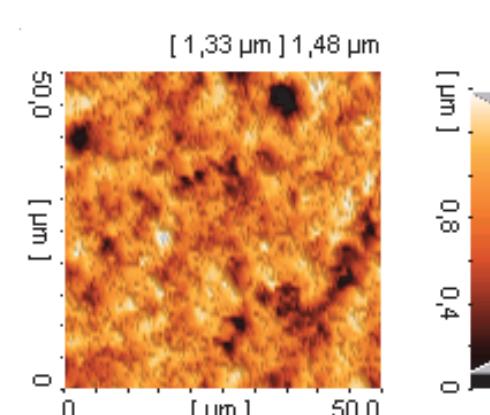
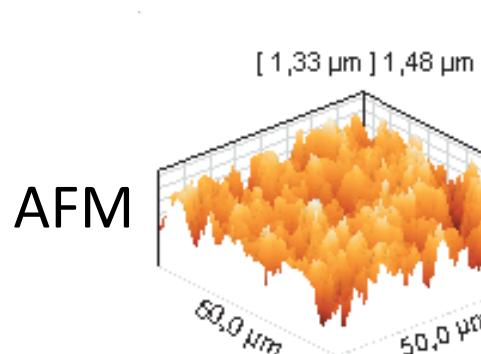
R&D on HPGe production technologies

First step:
we acquired the basic
know-how for the **in-**
house production of
commercial-like
planar HPGe
detectors.



- Mechanical treatment and chemical preparation of the surfaces
- n⁺ -contact made with Li diffusion doped method (600 - 900 μm thick)
- p⁺ -contact with B implantation (about 0.3 μ thick) + Au film deposition...
- Surface passivation & mounting

Mechanical treatment of the HPGe surfaces (lapping)

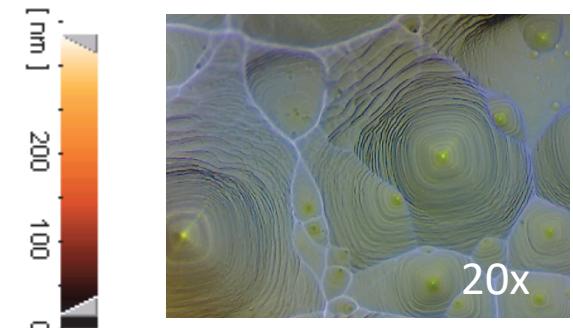
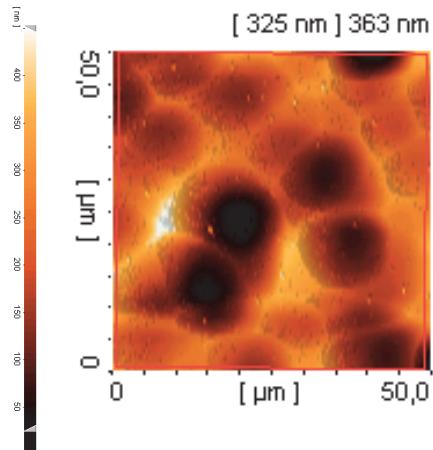
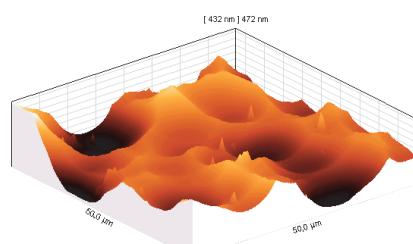


Roughness after lapping: 150 - 250 nm

Count of the crystal
dislocations



Chemical preparation of the HPGe surfaces (etching)

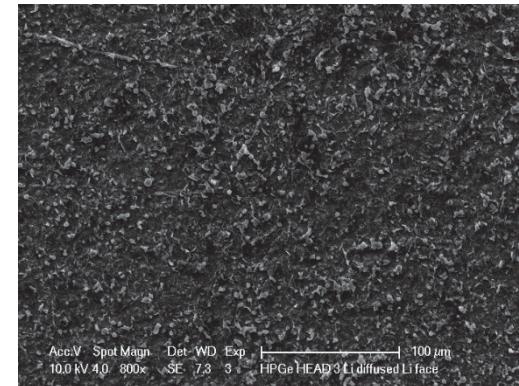


Roughness after etching: 50 - 100 nm

n+ -contact made with Li diffusion method



Evaporation
apparatus

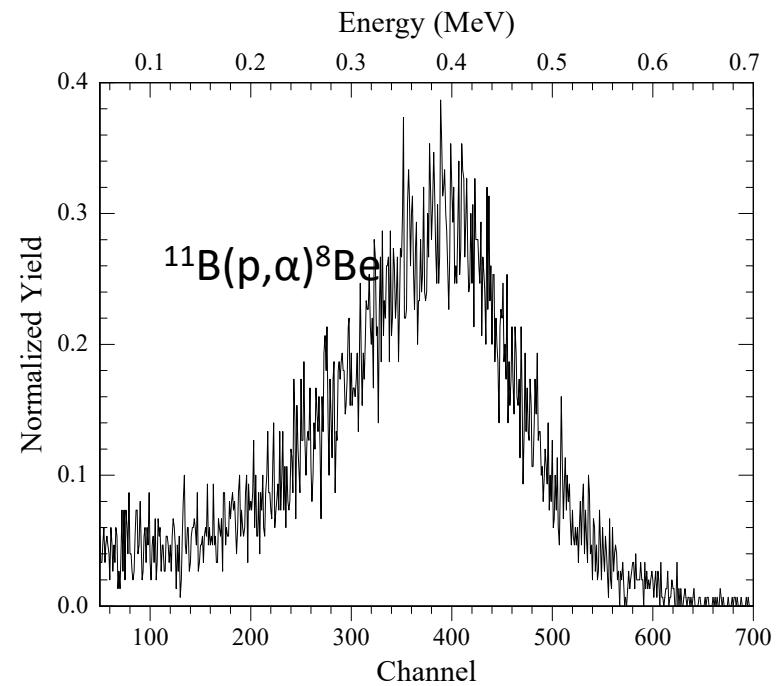


Li-coated surface

p+ -contact made with B implantation

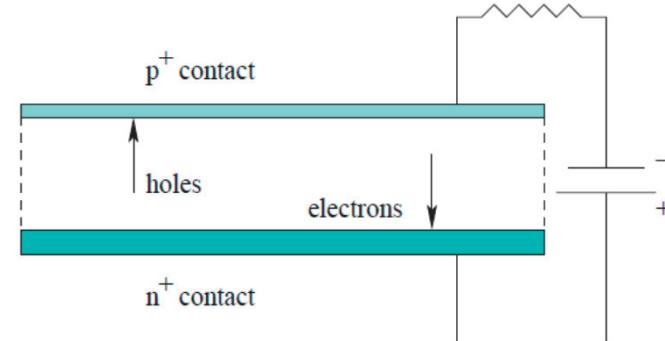
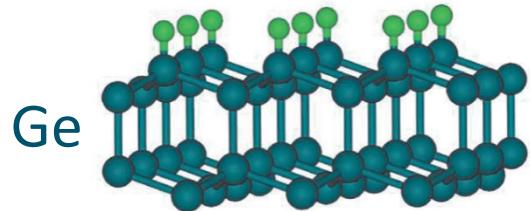


Ion implantation
apparatus



PASSIVATION

Passivation of the intrinsic surface



Ideal
Passivation

electrical: low leakage current

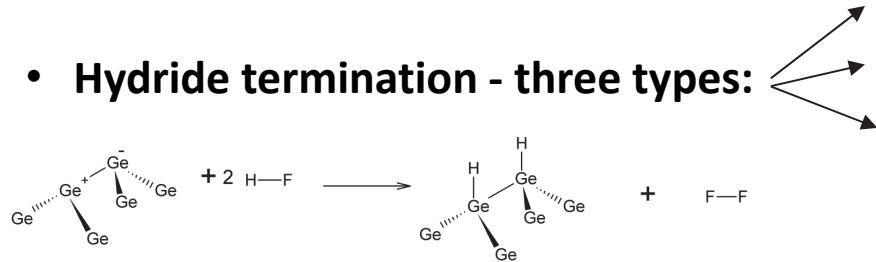
chemical: prevents the surface from reacting with the atmosphere

Ge is not like Si: natural Ge oxides are not stable

Some known passivations: SiO_2 or amorphous Ge(H)

Passivation techniques

- Hydride termination - three types:

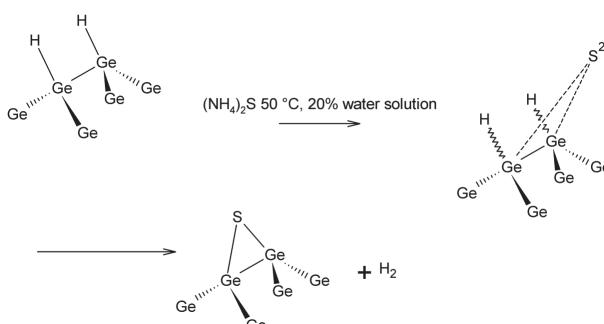


Low hydride (low concentration HF)

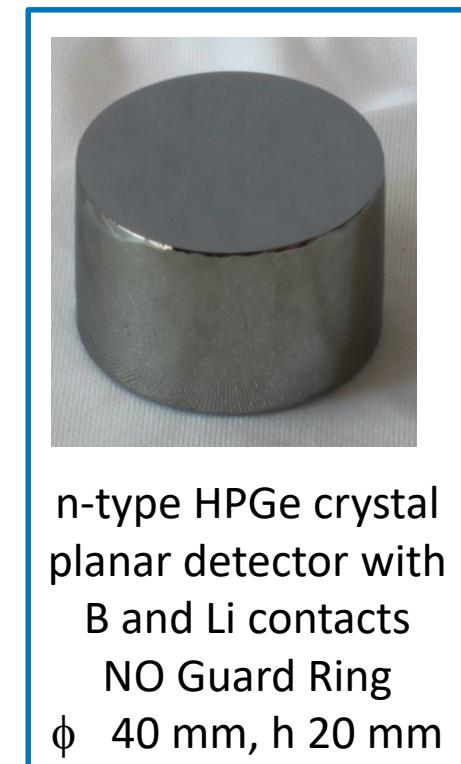
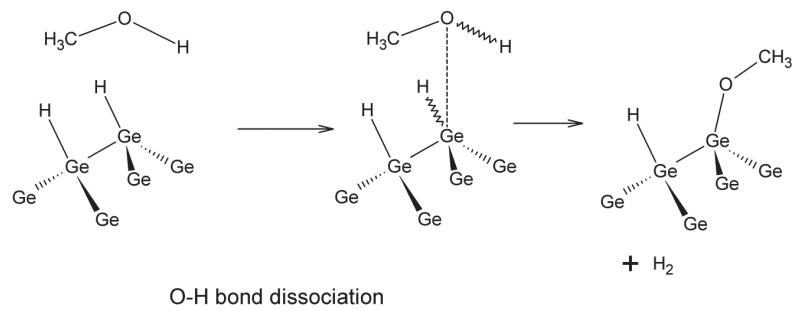
High hydride (high concentration HF)

Hyper hydride (same like High hydride but with after a different surface preparation)

- Sulfide termination $(\text{NH}_4)_2\text{S}$

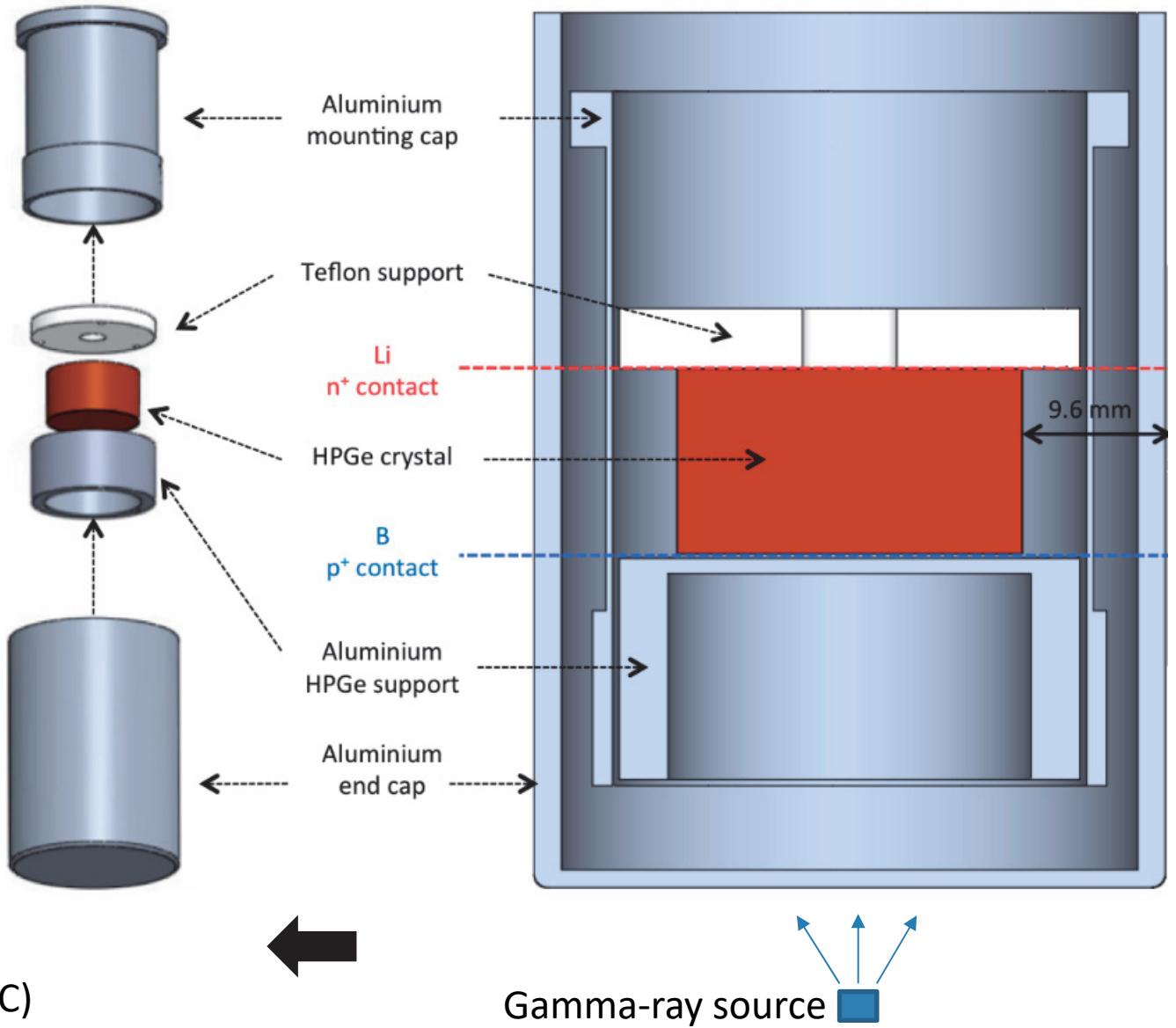
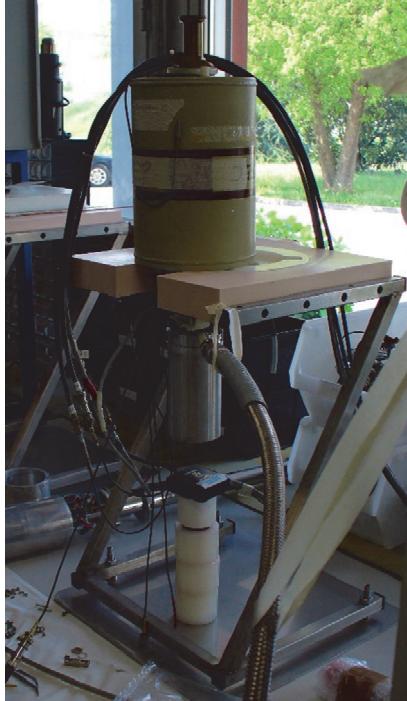


- Methanol Passivation (3:1 etching followed by methanol quenching)



The same detector was used for all the different passivation treatments to avoid bulk effects of the crystal and highlight surface effects.

Measurement setup for determining the detector bulk properties

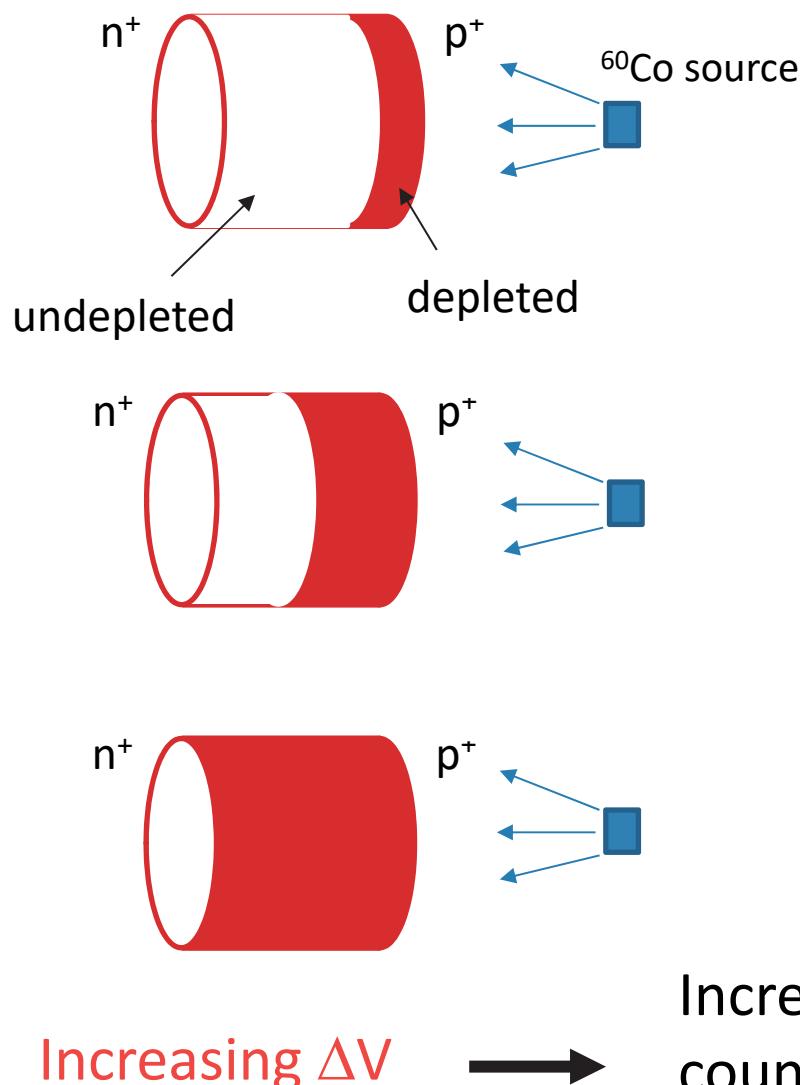


“Bulk” properties:

- Depletion voltage
- Efficiency
- Resolution
- Peak-to-Compton ratio (P/C)

Depletion voltage

How can we measure it?



Depletion voltage: the voltage at which the depletion depth is equal to the detector thickness

If surface effects can be neglected

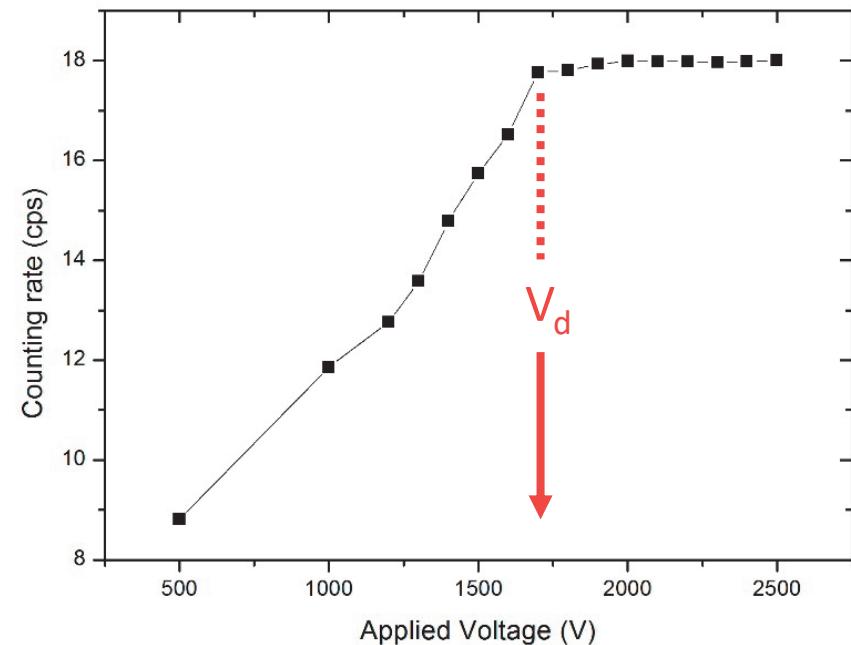
$$V_d = N q d^2 / 2 \epsilon$$

N = impurity density in the bulk

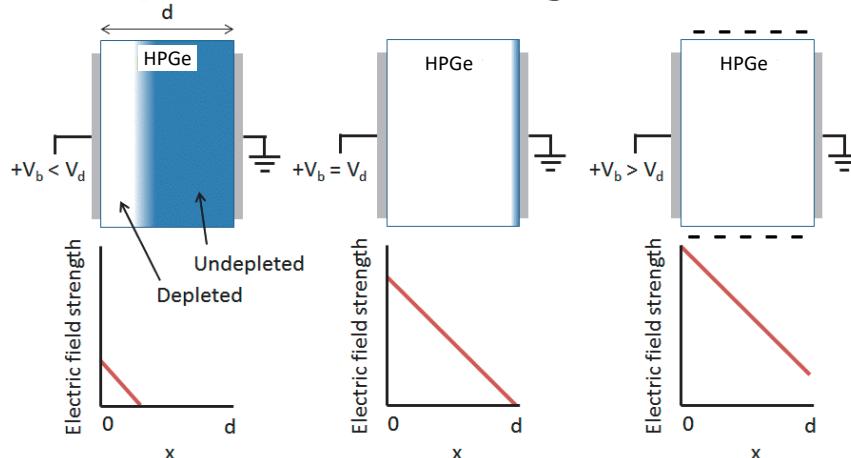
q = electronic charge

d = detector thickness

ϵ = dielectric constant of germanium



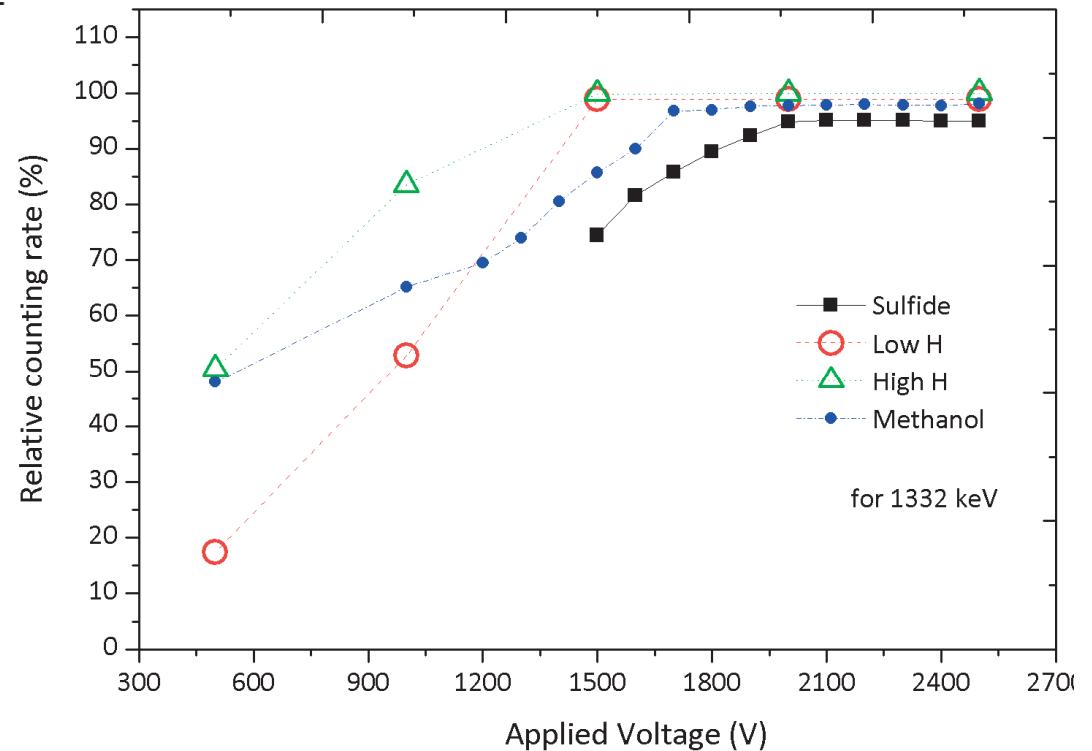
Depletion voltage



	Depletion Voltage (V)
Low H	≤ 1500
High H	≤ 1500
Methanol	1700
Sulfide	2000

Experimental results

(from G. Maggioni et al., EPJA 2015)



Surface effects are important



Passivation can give rise to a charge accumulation, which distorts the local field

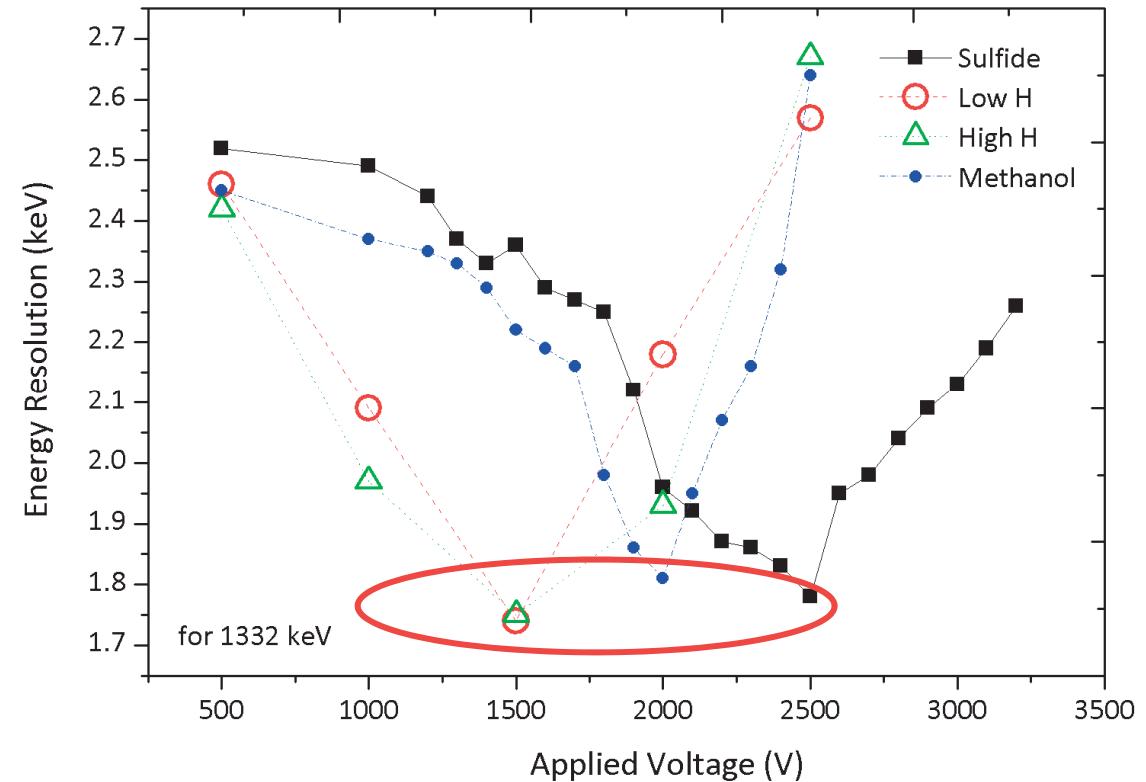
Plateau value of counting rate for sulfide is lower → lower active volume (90-95%)

Detector resolution (FWHM) vs bias voltage

Detector exposed to
a ^{60}Co source

Resolution ranges
from 1.7 to 2.7 keV

	Voltage for best resolution (V)
Low H	1500
High H	1500
Methanol	2000
Sulfide	2500



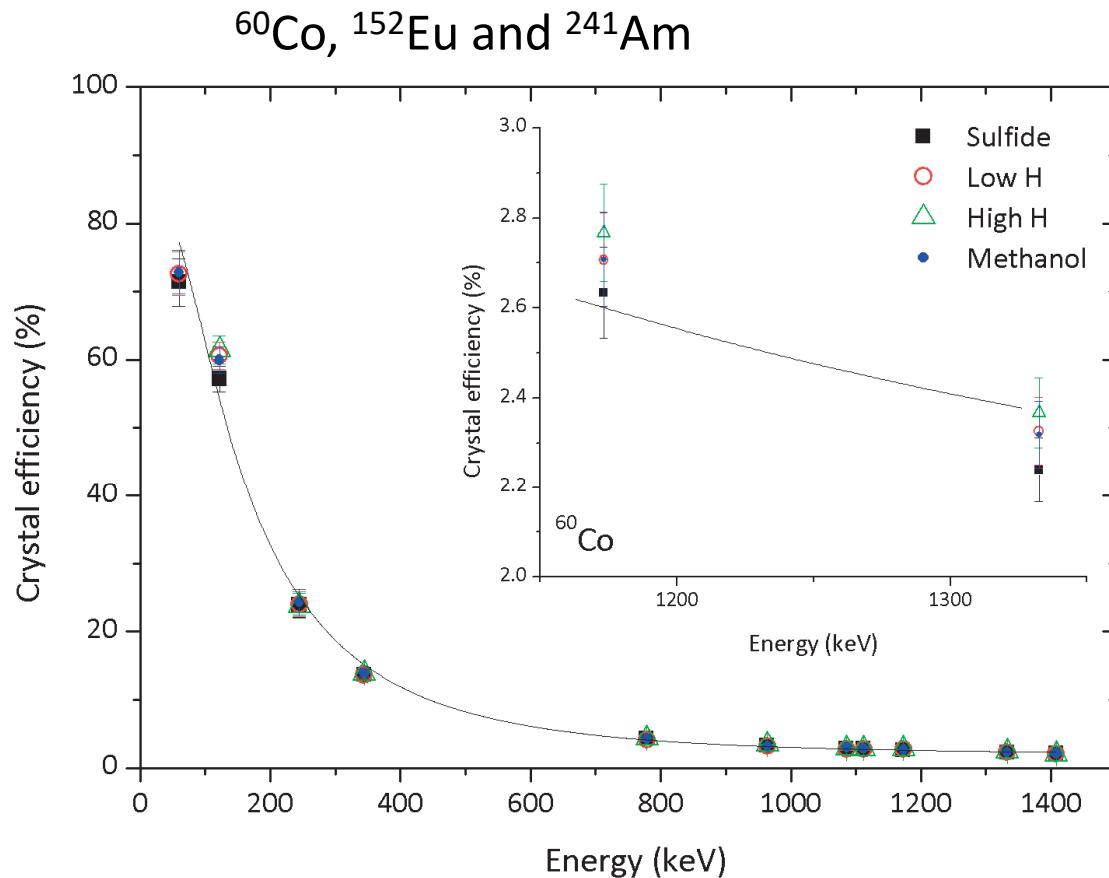
The best resolution is comparable for all the passivations

Detector efficiency

$$\epsilon_{exp} = \frac{R}{A \times I \times \exp(\sum_{i=1}^3 -(\mu_i \times d_i) \times (\Omega/4\pi))}$$

R = counting rate
A = source activity
I = emission probability of the line of interest
 d_i and μ_i = thickness and total absorption coefficient of the absorbing layers, respectively
 Ω = solid angle subtended by the detector

(from A. Elanique et al., Appl. Rad. Isot. 2012)

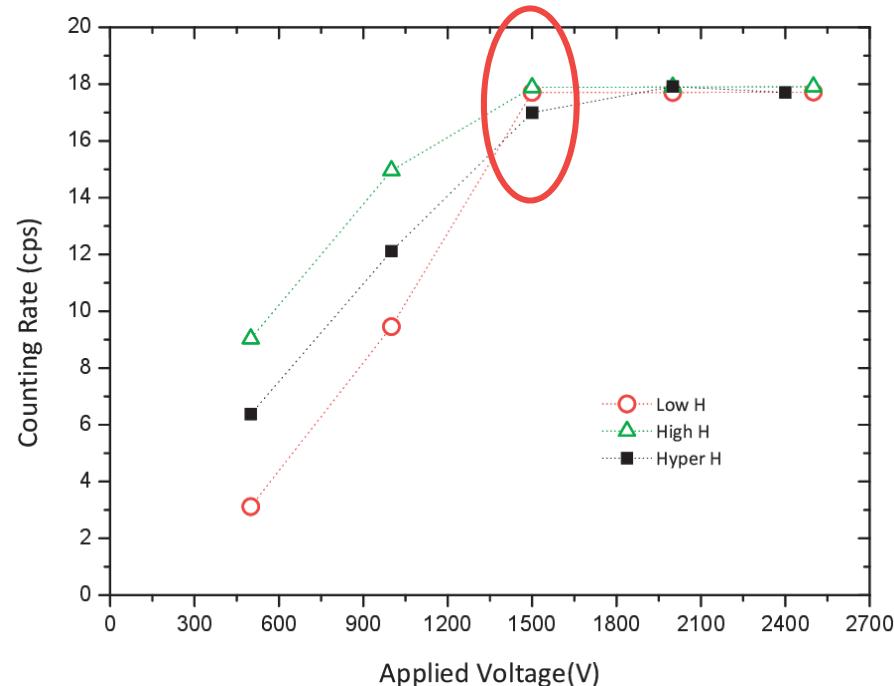


Surface passivation
slightly affects the
detector efficiency

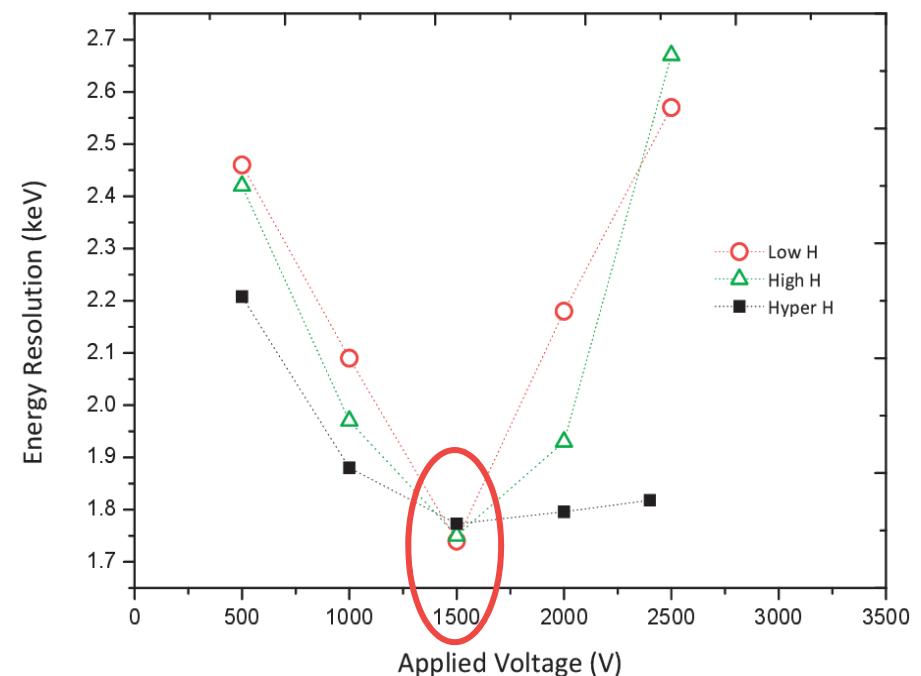
Detector properties and surface passivation: current results

Passivations: Low H, High H and Hyper H

Depletion Voltage

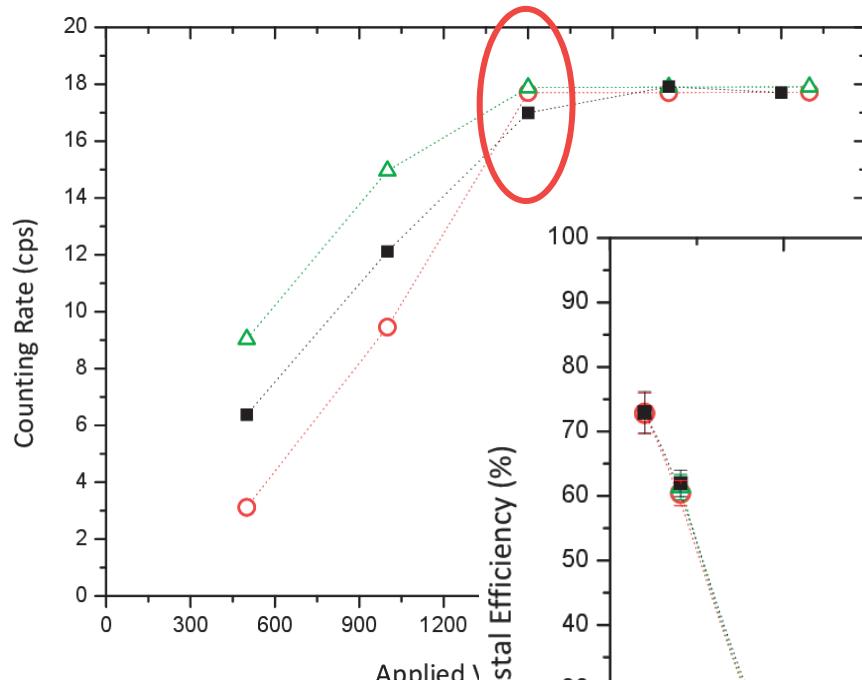


Energy Resolution

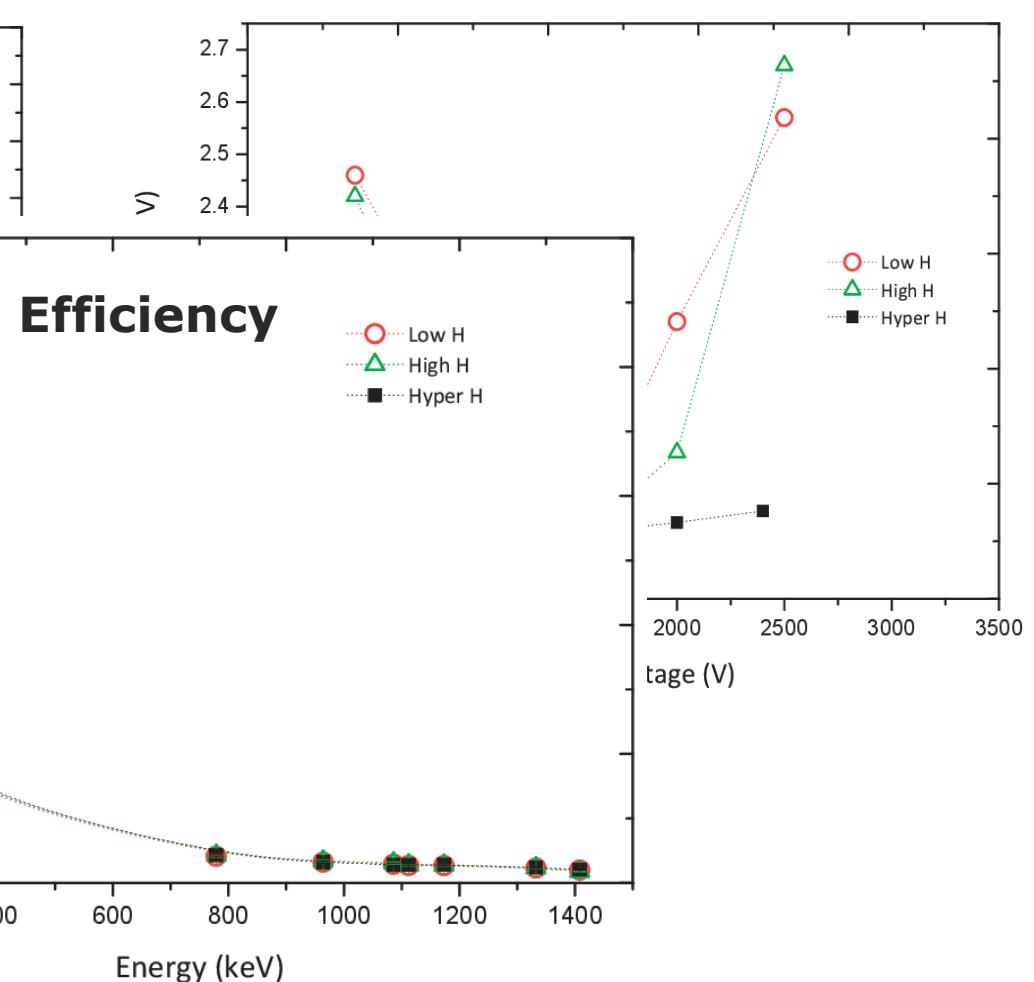


Passivations: Low H, High H and Hyper H

Depletion Voltage



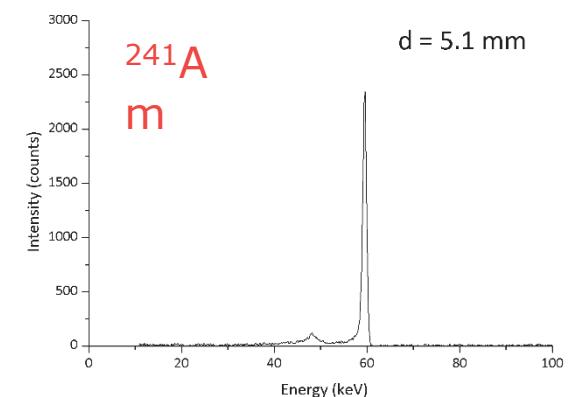
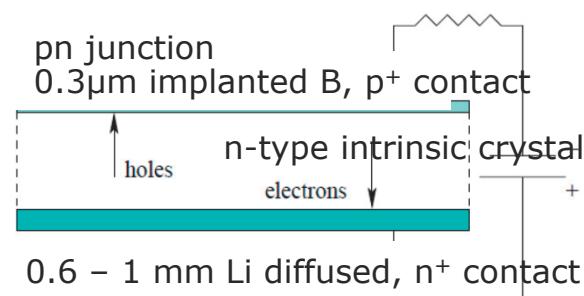
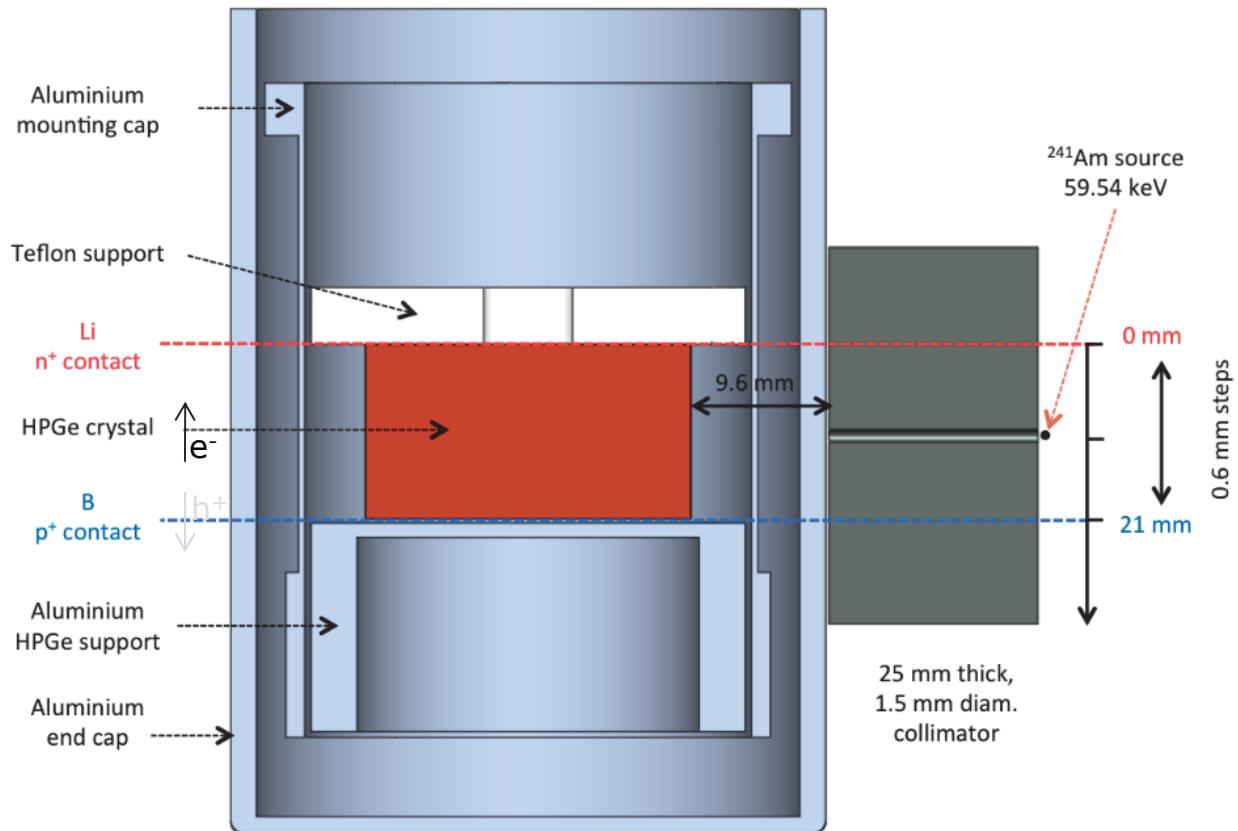
Energy Resolution



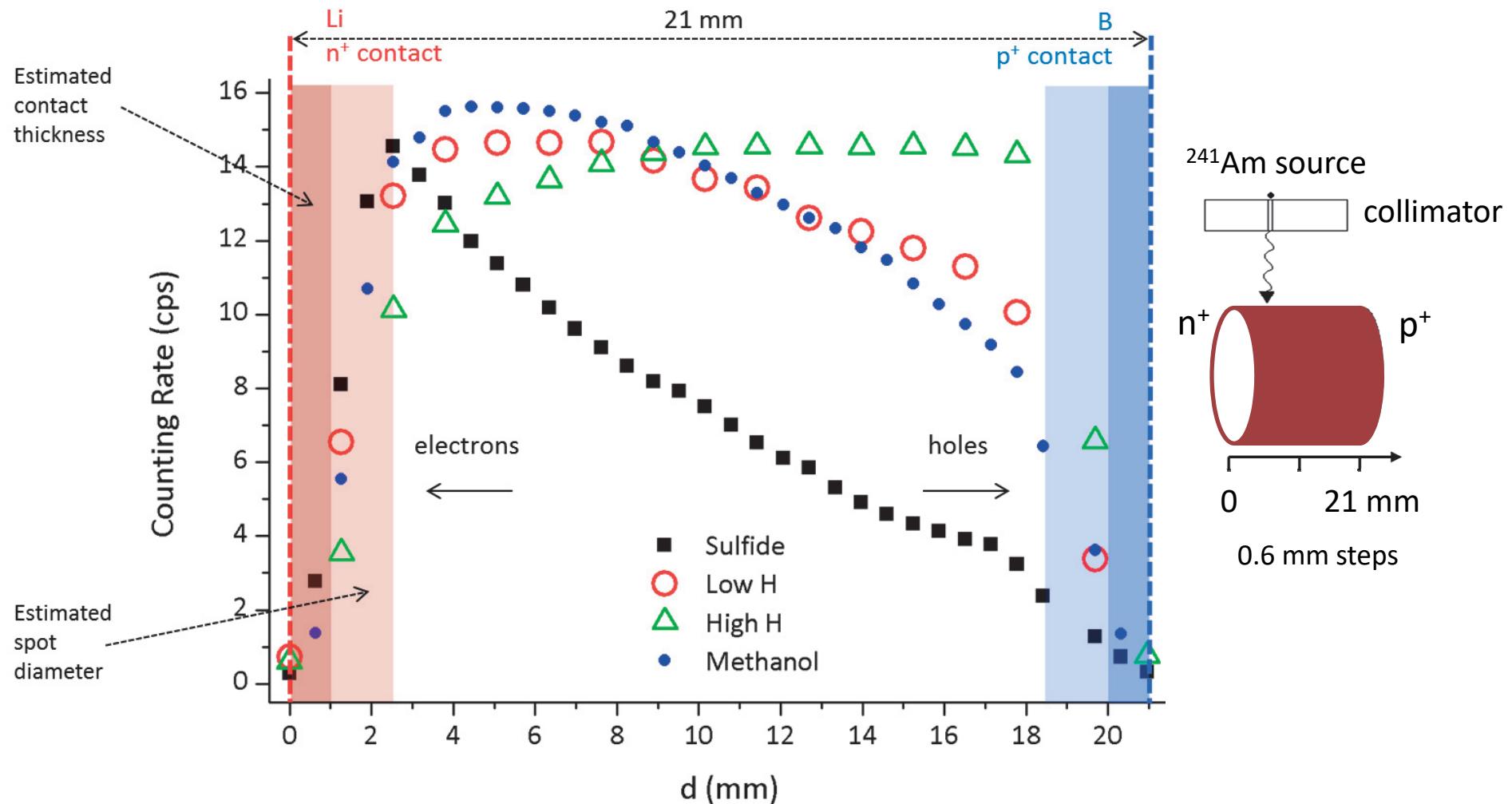
(from S. Riccetto et al., to be submitted to **EPJA**)

Lateral scan with 60eV γ -rays

Lateral scans with a Collimated ^{241}Am Source to study the passivated surface.

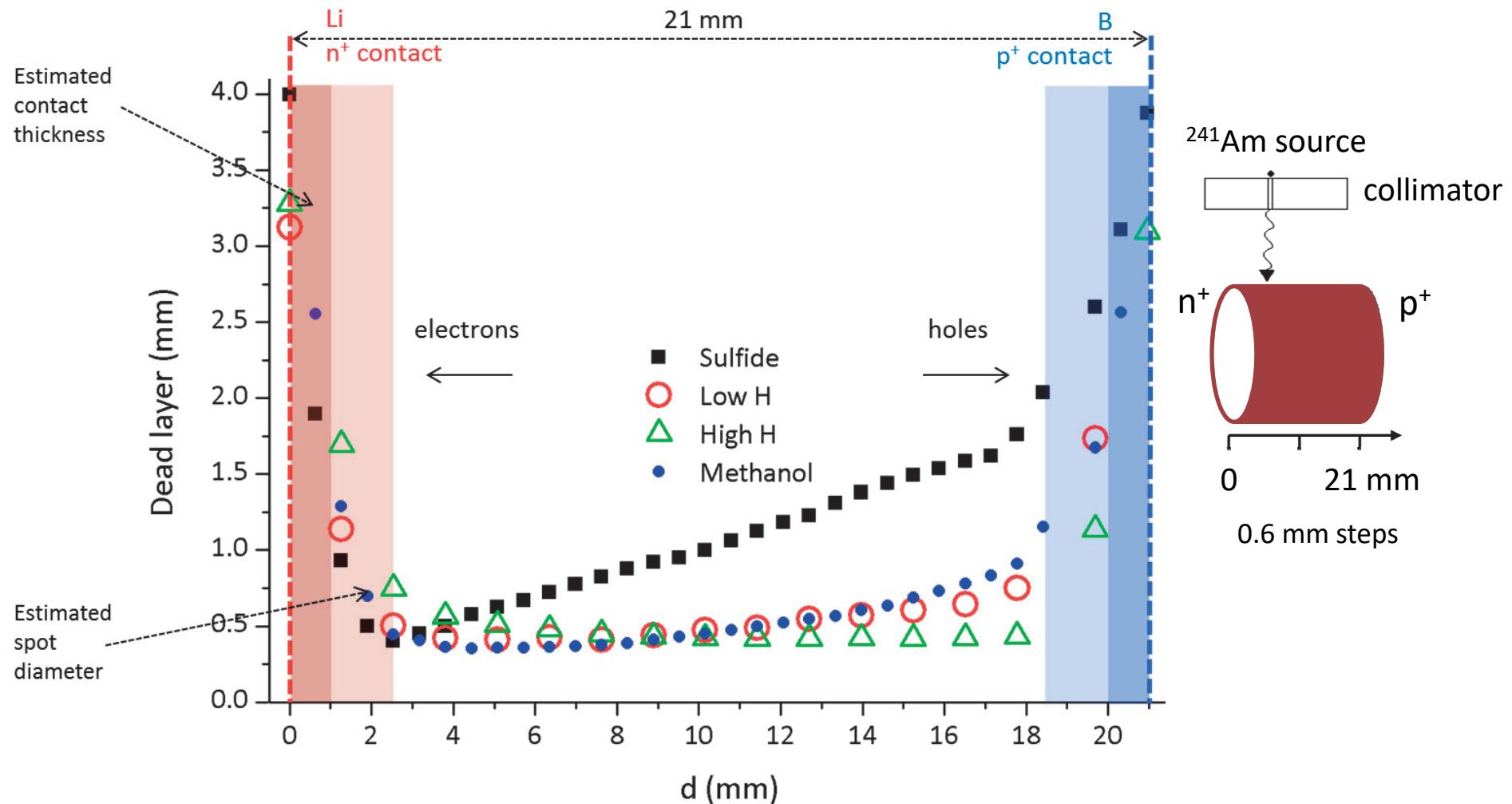


Scan of the passivated surface: counting rate vs distance



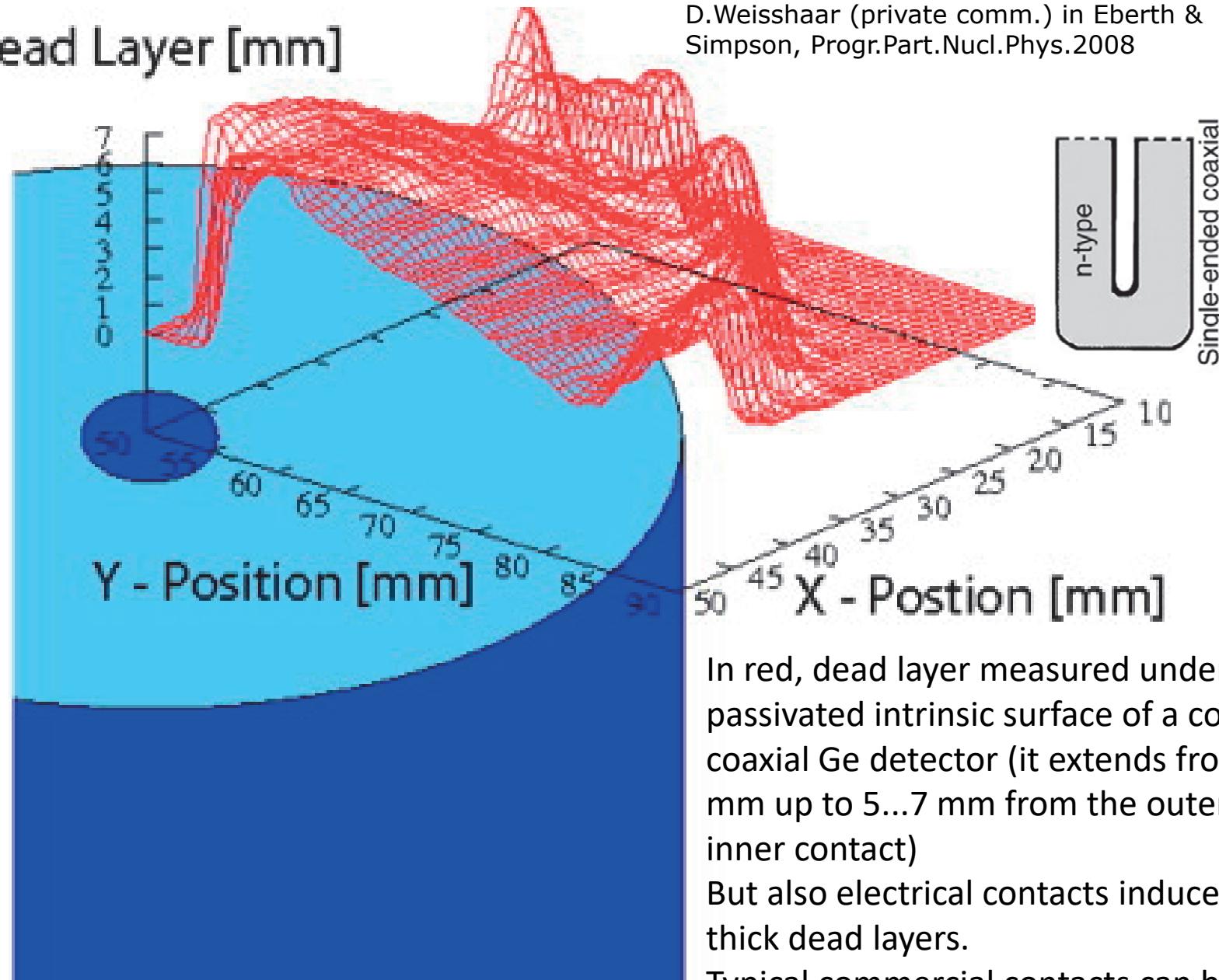
- Strong decrease of counting rate close to the electrodes
- S-terminated detector: n-type surface behavior, which can be related to a negative charge accumulation
- For the other passivations the n-type/p-type behavior is less pronounced

Scan of the passivated surface: dead layer vs passivation

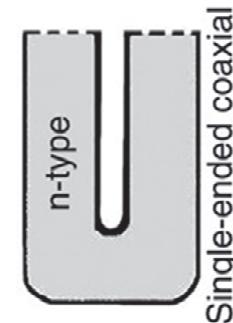


- The average dead layer is below 1 mm, except for S-terminated detector
- The difference in dead layer thickness involves a difference in the active volume, which can reach 10% in the case of the S-terminated detector

Dead Layer [mm]



D.Weisshaar (private comm.) in Eberth & Simpson, Progr.Part.Nucl.Phys.2008



We need to reduce dead volumes inside the detector!

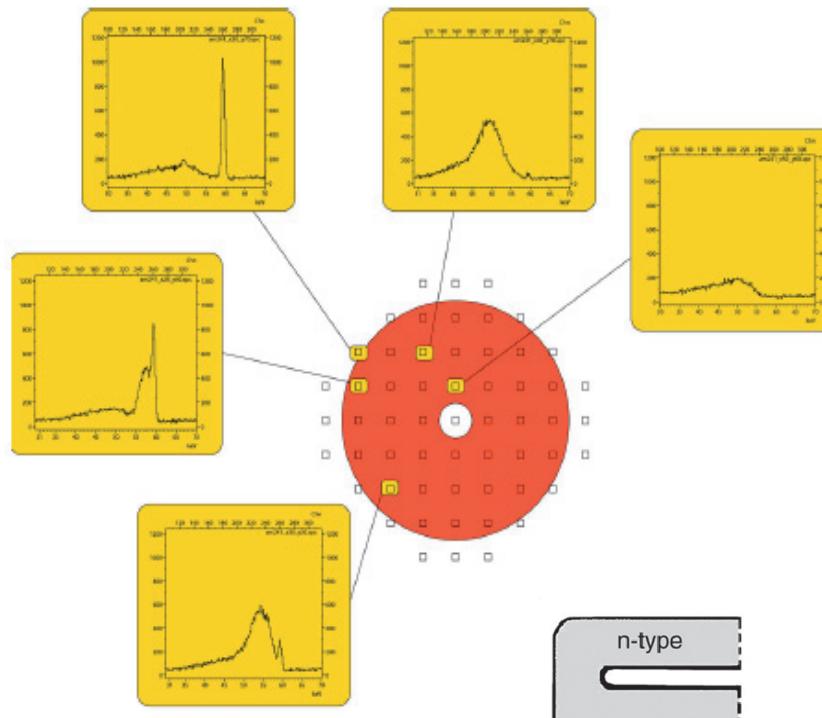
In red, dead layer measured under the passivated intrinsic surface of a commercial coaxial Ge detector (it extends from 1...2 mm up to 5...7 mm from the outer to the inner contact)

But also electrical contacts induce relatively thick dead layers.

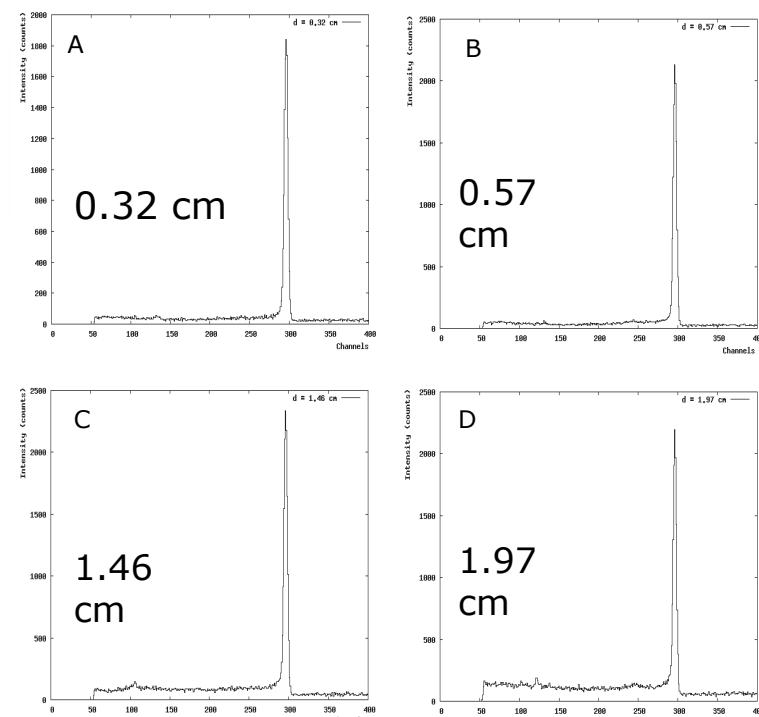
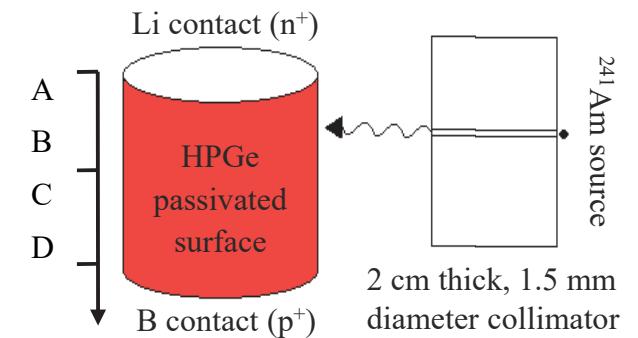
Typical commercial contacts can be: Li, B, a-Ge(H), a-Si(H), Y, etc.

Incomplete charge collection near the passivated surface

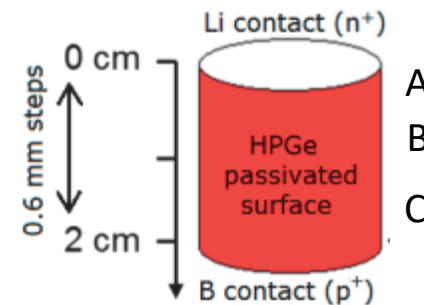
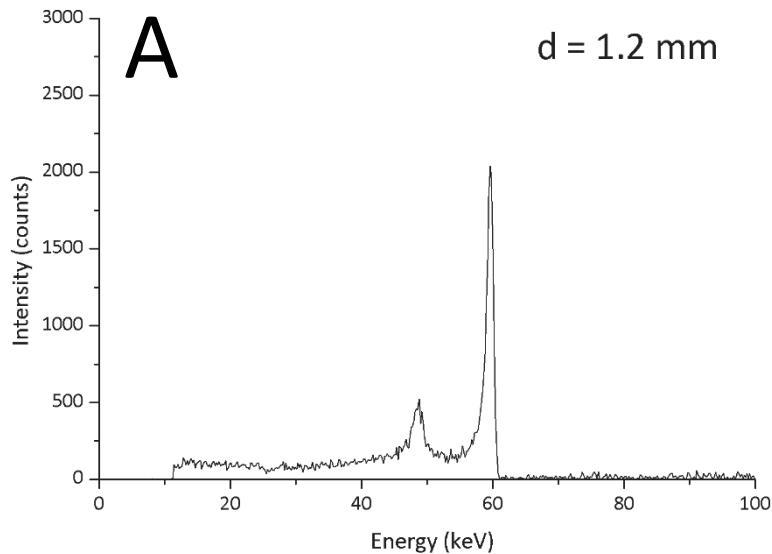
Comparison between an LNL prototype
and a commercial detector



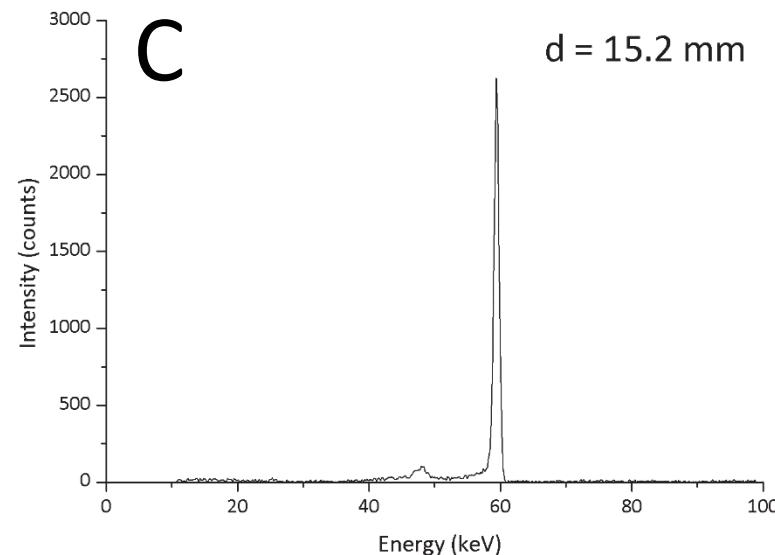
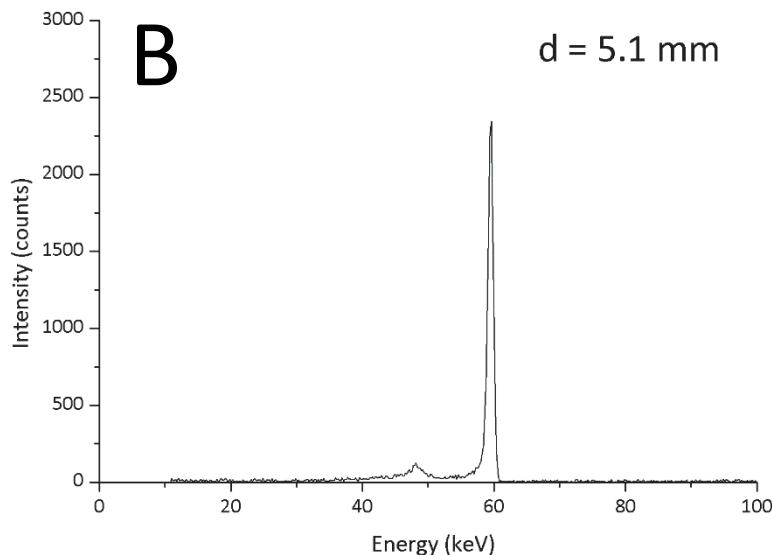
from D. Weisshaar (private comm.) in
J. Eberth and J. Simpson, Progress in
Particle and Nuclear Physics 60(2008)283



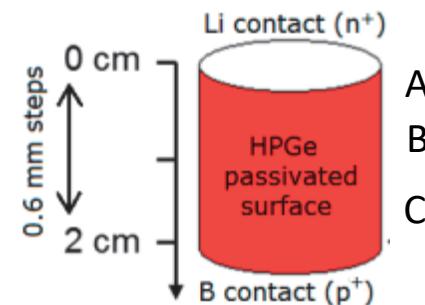
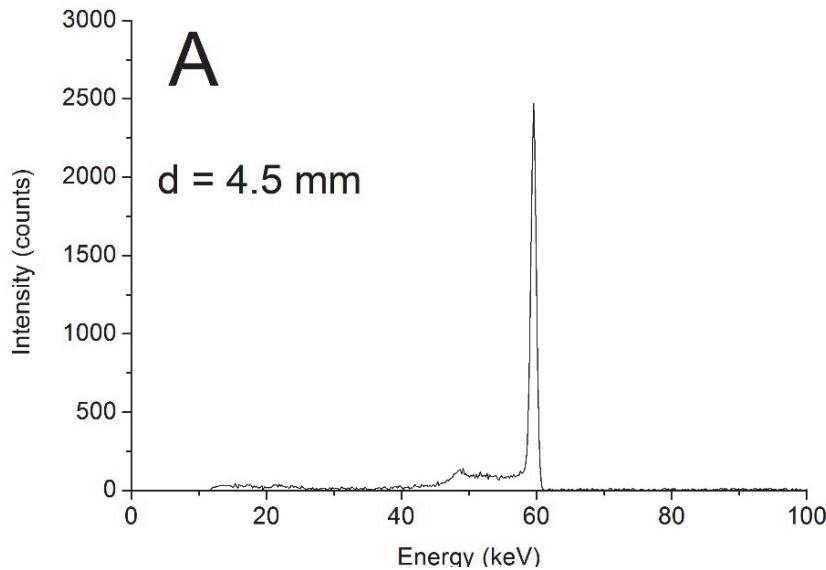
High H-passivated detector: ^{241}Am spectra



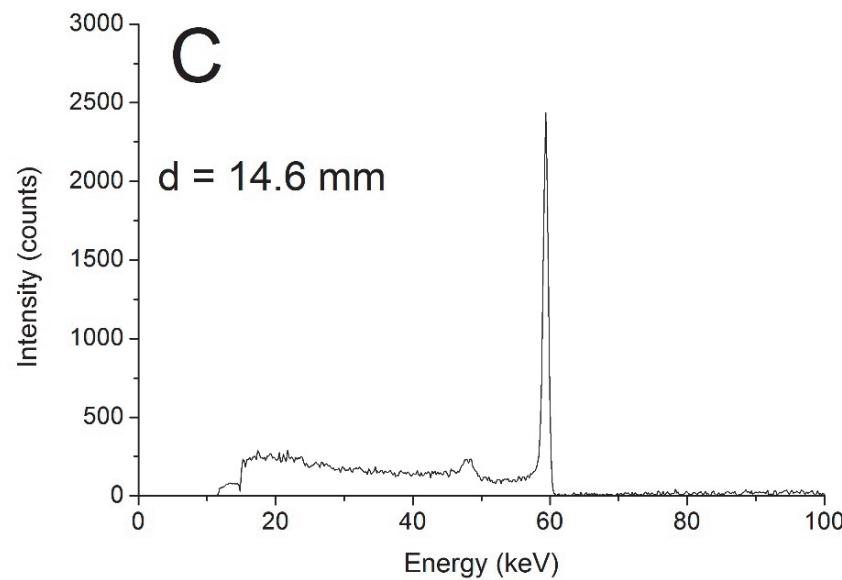
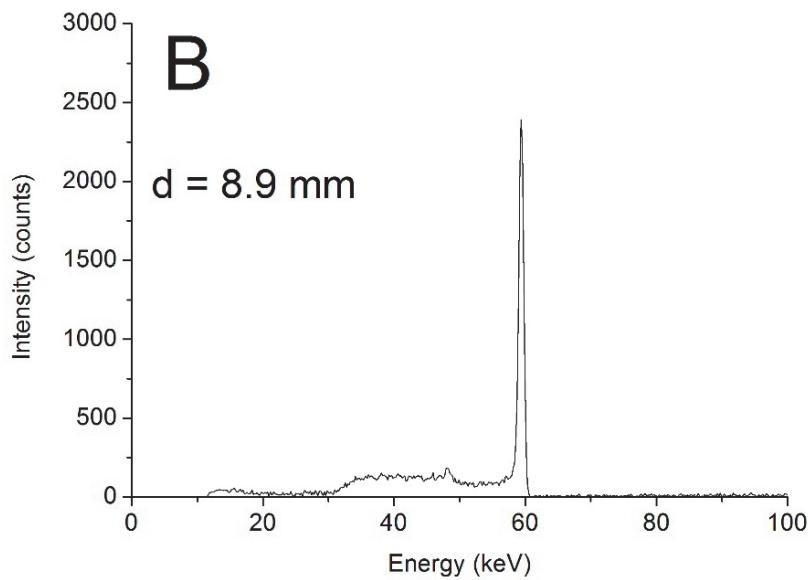
Constant photopeak area normalization



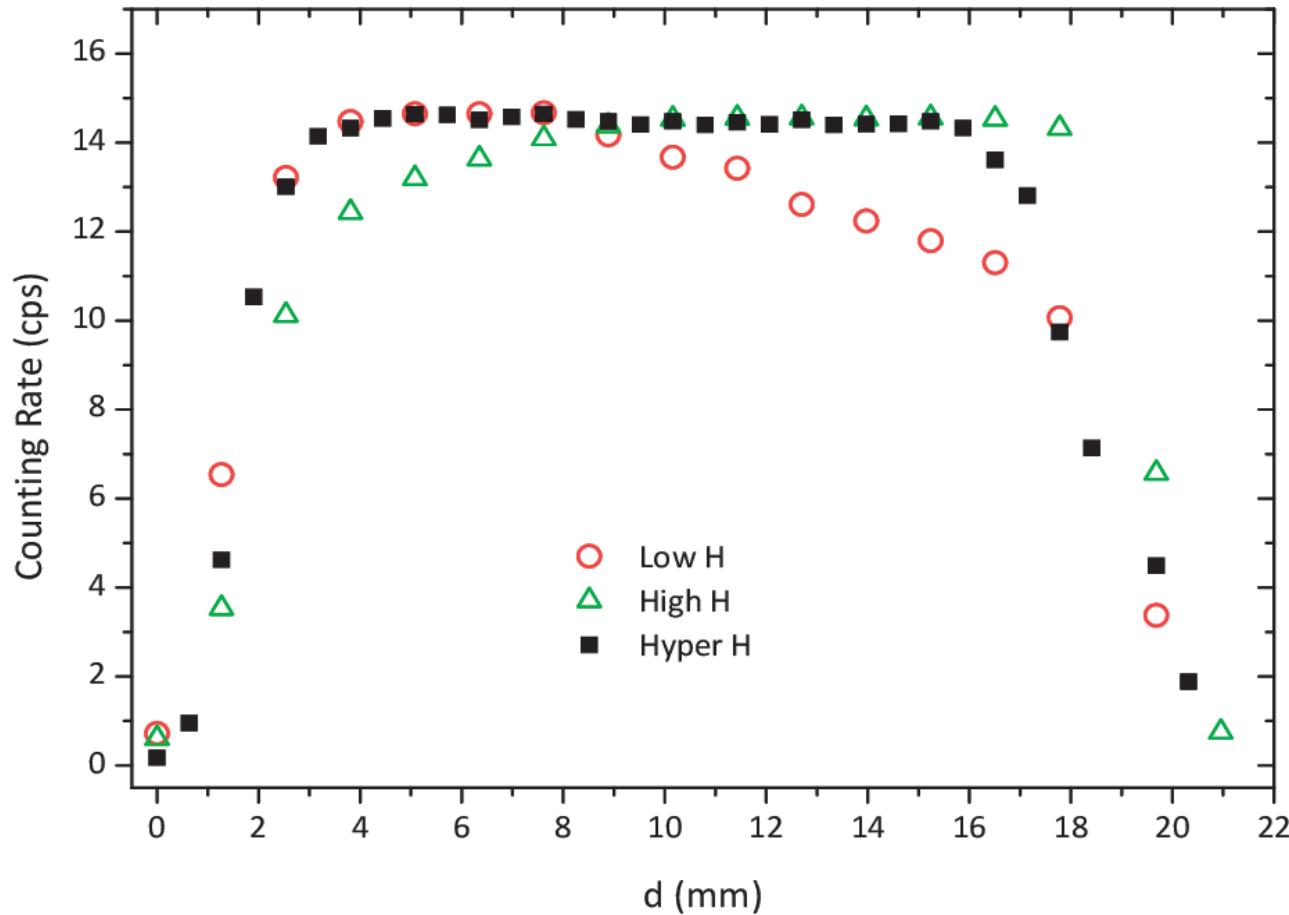
Sulfide passivated detector: ^{241}Am spectra



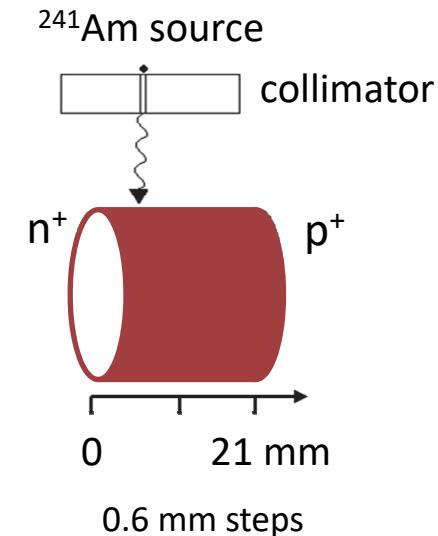
Constant photopeak area normalization



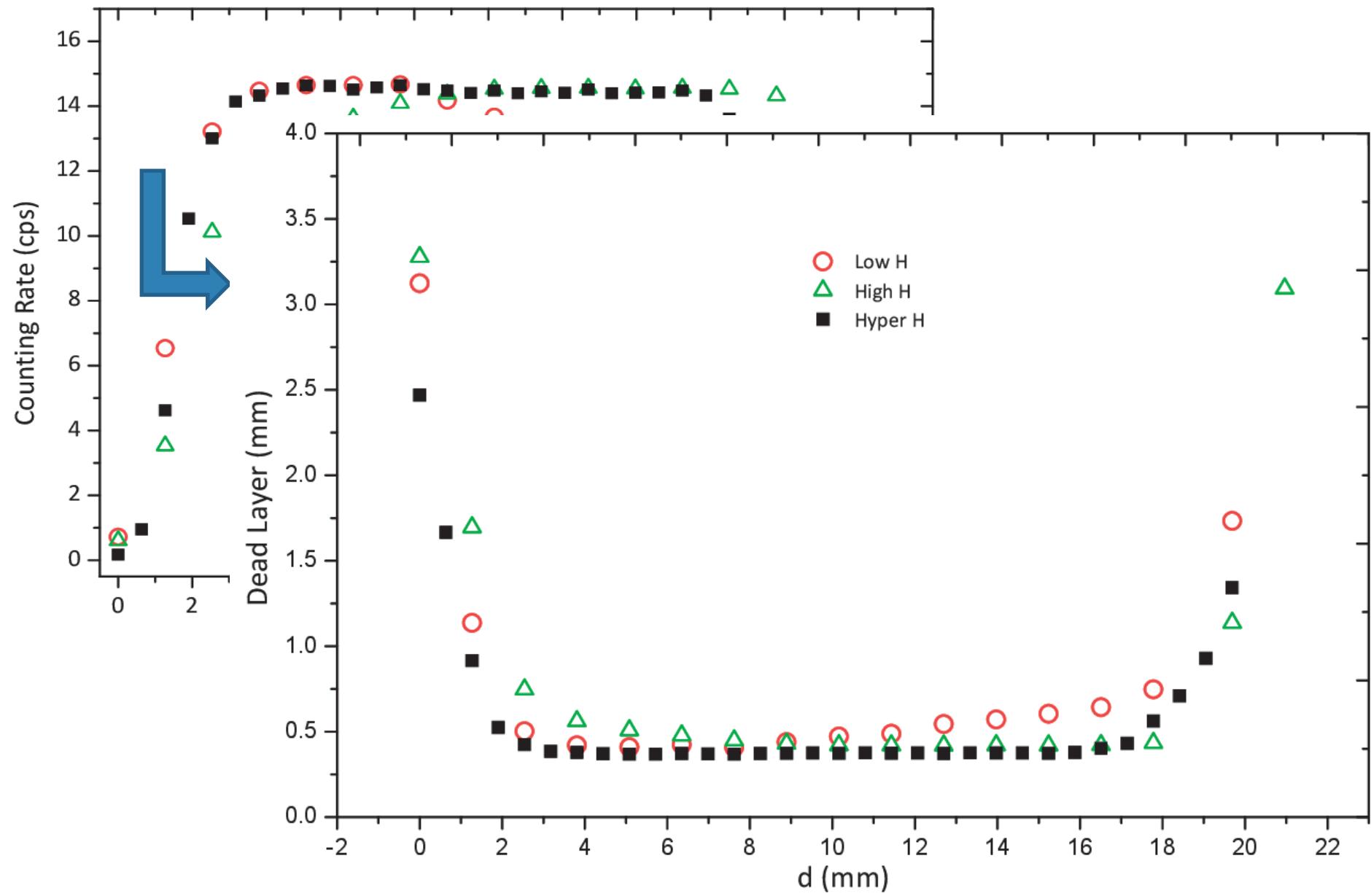
Scan of the passivated surface: counting rate



- Low H: slightly n-type surface
- △ High H: slightly p-type surface
- Hyper H: essentially “neutral”



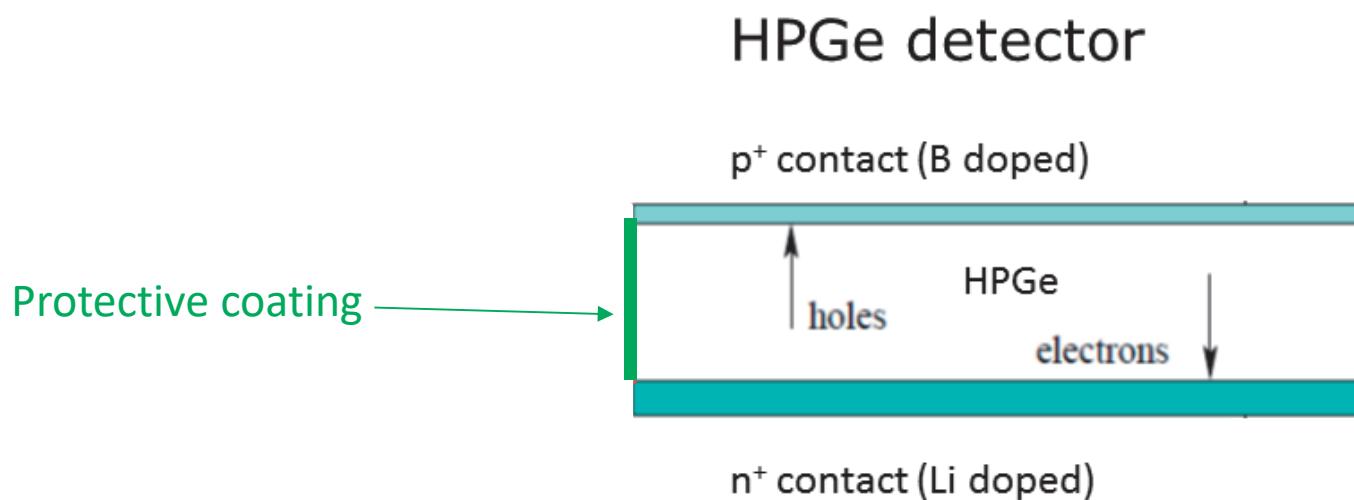
Hyper H: the smallest dead volume



Problem: all these passivations are not stable



Solution: New protective coating

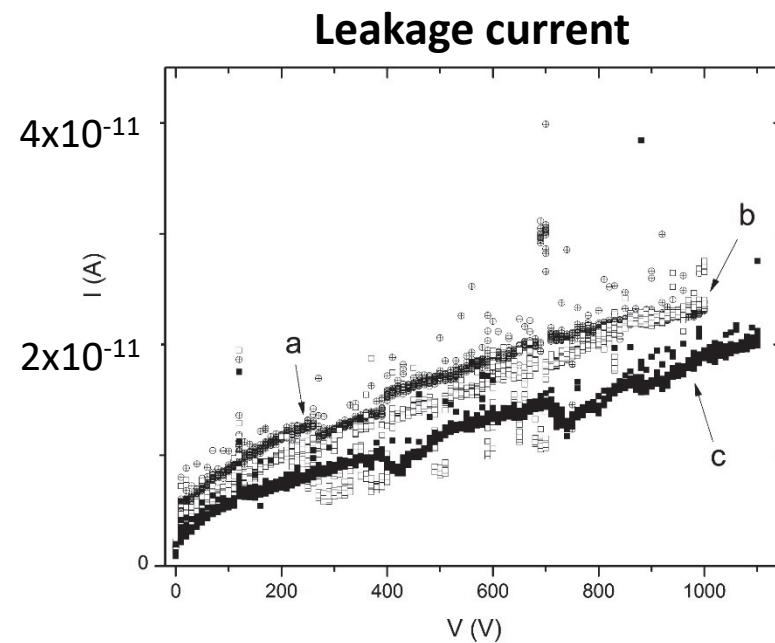
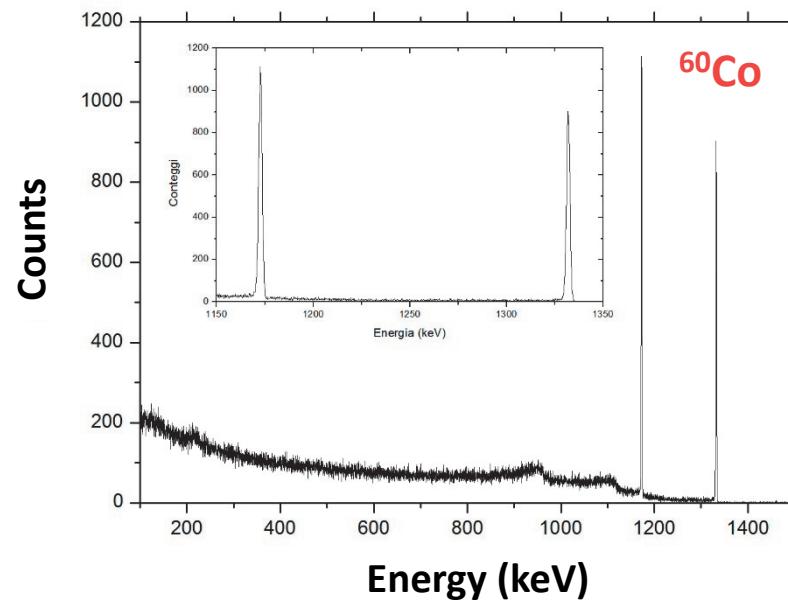


Preliminary tests of coated detectors

- ✓ Methanol passivation followed by the protective coating application
 - 19 months at room temperature under static vacuum
 - 10 minutes at room temperature on the desk
 - 40 hours at 103°C under vacuum



The properties of the coated detector do not change after these tests



NOVEL CONTACTS

Development of novel contacts

Thermally-induced dopant diffusion



Thermally-induced contamination

(Impurity diffusion inside semiconductors is a thermally activated process)

Which one of them is predominating?

“Thermal process window”?

List of studied processes

- P diffusion by Spin-On-Doping [V. Boldrini et al., Appl. Surf. Sci. 392 (2017)]
- ✳ Sb diffusion from a remote sputtered source [G. Maggioni et al., MSSP (2018)]
- ✳ High-T annealing treatments on as cut samples

- Temperature range: from 600 to 810°C
- Time range: from 2 to 30 minutes

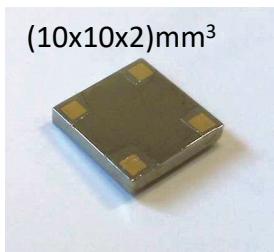
- Reference samples:
 - n-type HPGe
 - p-type HPGe
 - B ion implanted (23 keV, 1e15 cm⁻²)



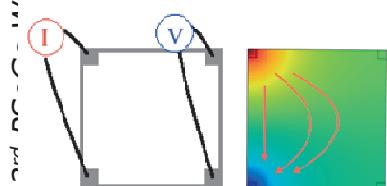
Supplied by Umicore

Contamination of HPGe – LTA technology

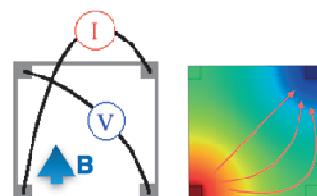
Four-wire resistance and Hall measurement



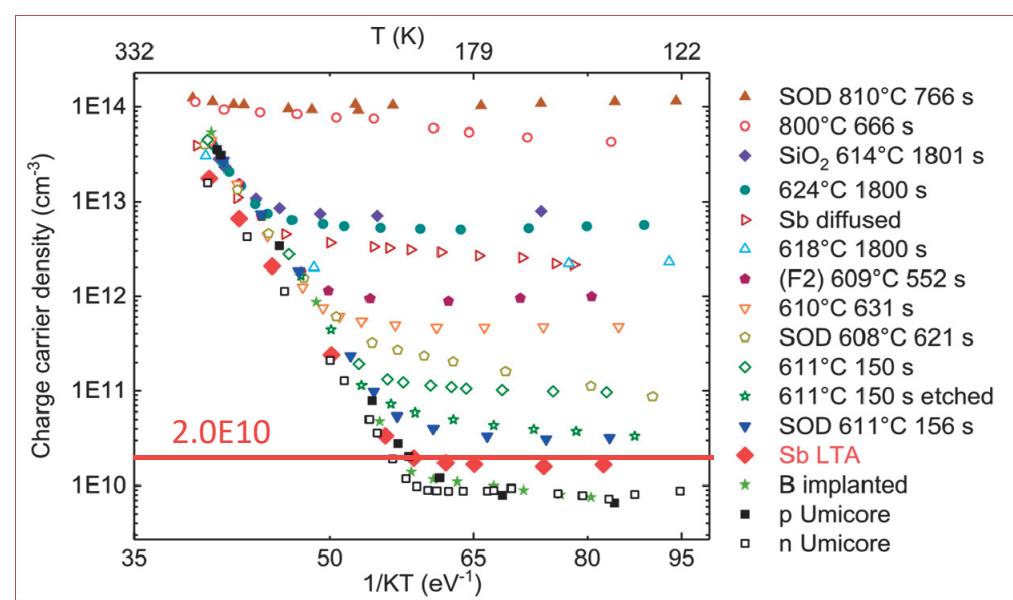
van der Pauw method
 R_{sheet}



Hall-effect method
Carrier type

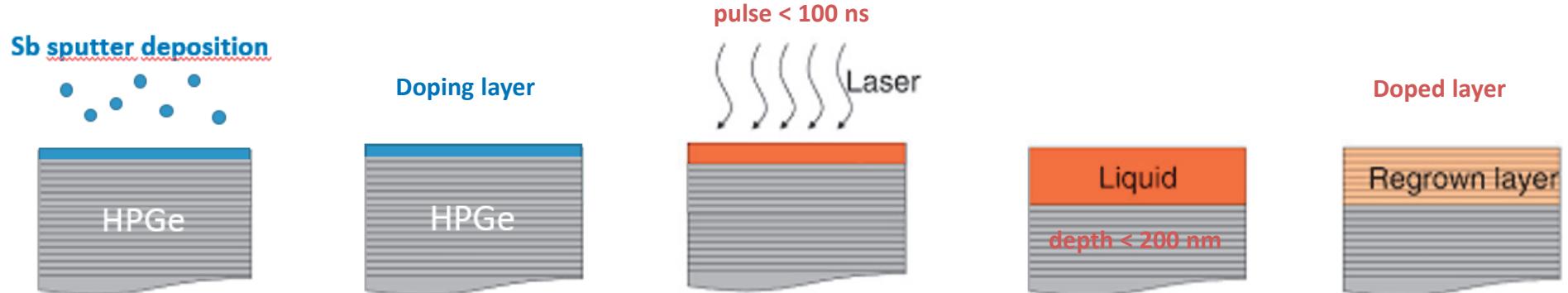


Contamination after laser treatment



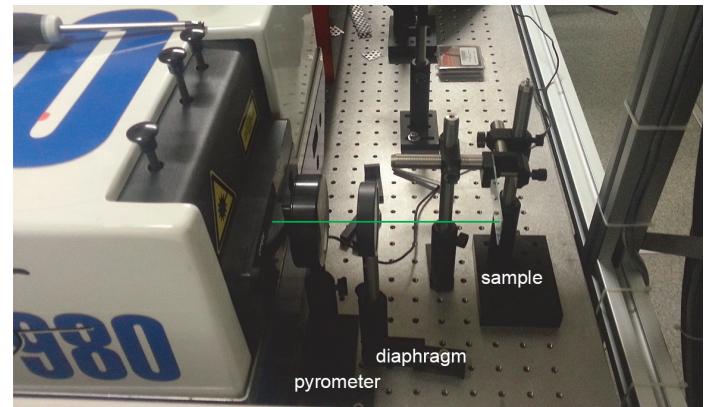
[From V. Boldrini et al., Mater. Sci. Semicond. Proc. (2018), submitted]

n⁺ contact on HPGe – LTA technology



Advantages:

- Melting temperature is reached and maintained for a short time (<100 ns)
- Only the surface (< 200 nm) is melted, the bulk is at room temperature
- High dopant concentrations → → near-ideal p-n- junctions
- Doping with heavy elements without crystal damage
- Very clean process suitable for preserving the Ge hyperpurity
- Suitable for complex contact geometries (segmentation)



Pulsed Laser @ LNL-INFN

Nd:YAG

$\lambda=355 \text{ nm}$ (third harmonic generator)

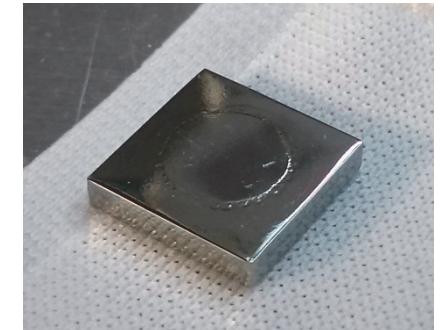
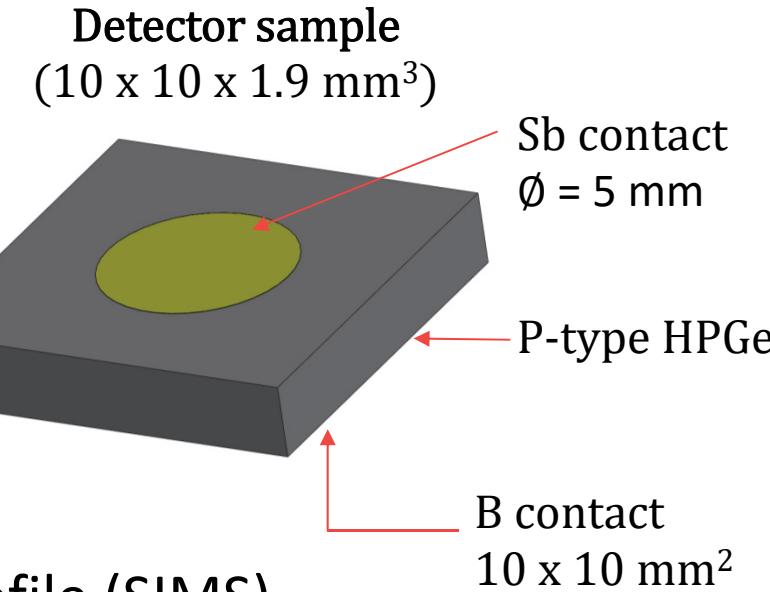
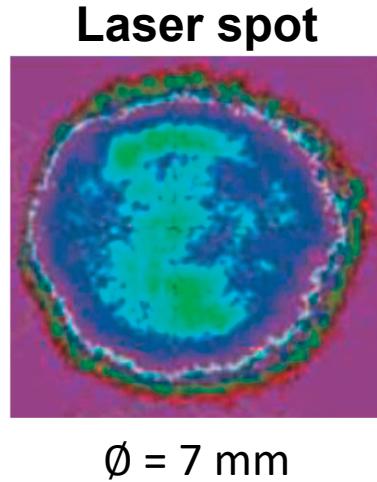
$\tau=7 \text{ ns}$; $\emptyset=6,5 \text{ mm}$; Rate = 10Hz

Radiant power ~1500 mW

Fluence ~300-400 mJ/cm²

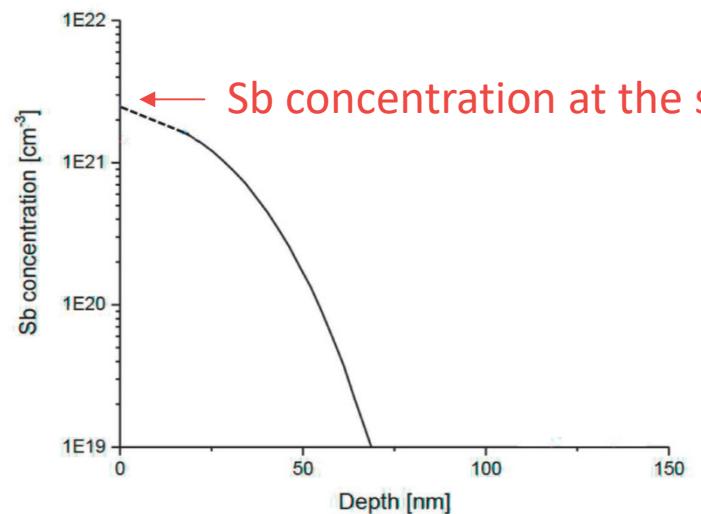
The small detector prototype

Laser geometry was favoured at the expense of detector performance



No guard ring

Sb diffusion profile (SIMS)



Contact thickness: $\leq 100 \text{ nm}$

Electrical activation of dopant

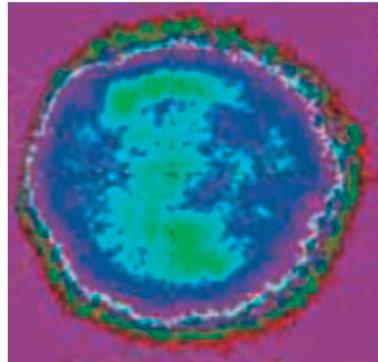
Preliminary data: > 50%

→ **High fraction of substitutional Sb**

The small detector prototype

Laser geometry was favoured at the expense of detector performance

Laser spot



$\varnothing = 7 \text{ mm}$

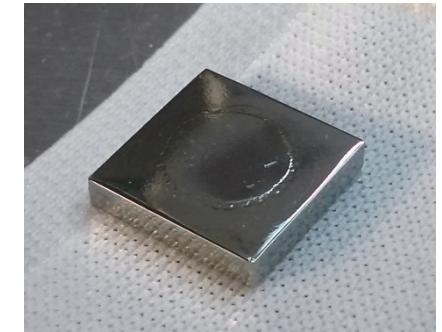
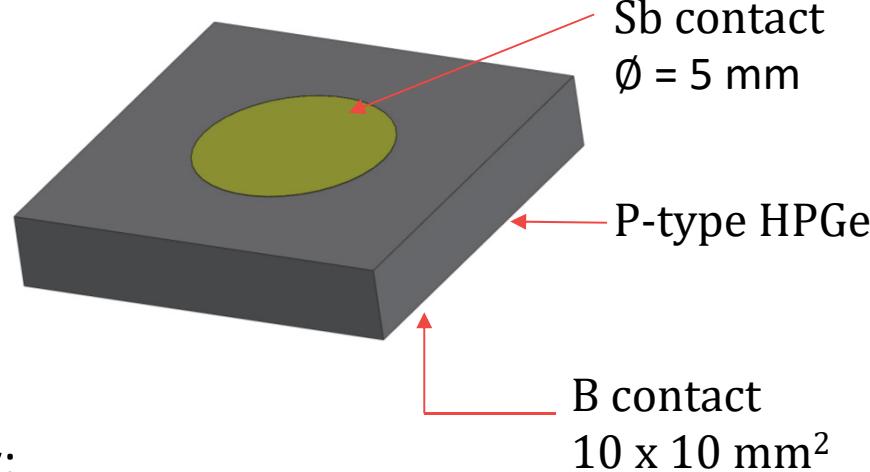
Surface morphology:
No laser-induced defects

SEM



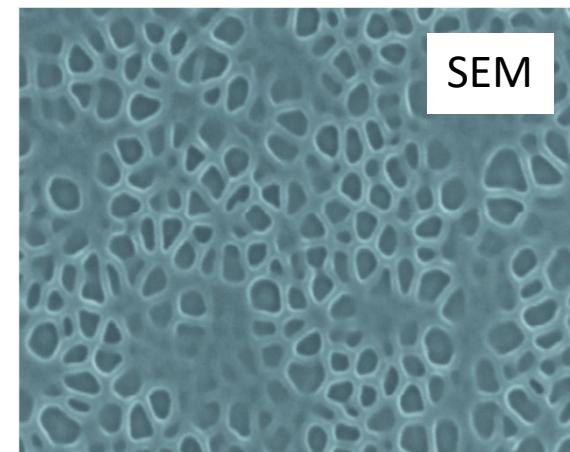
Detector sample

(10 x 10 x 1.9 mm³)



No guard ring

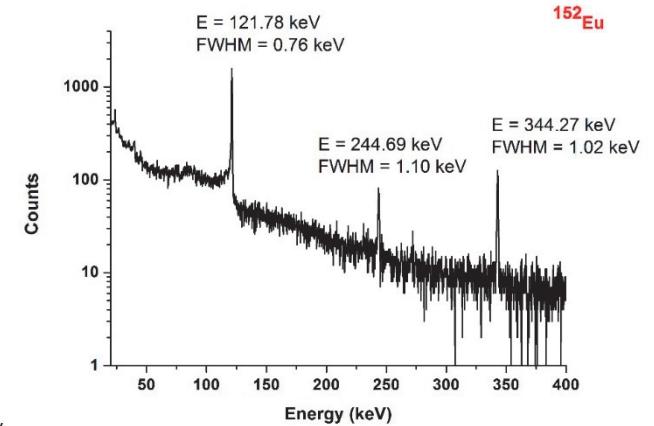
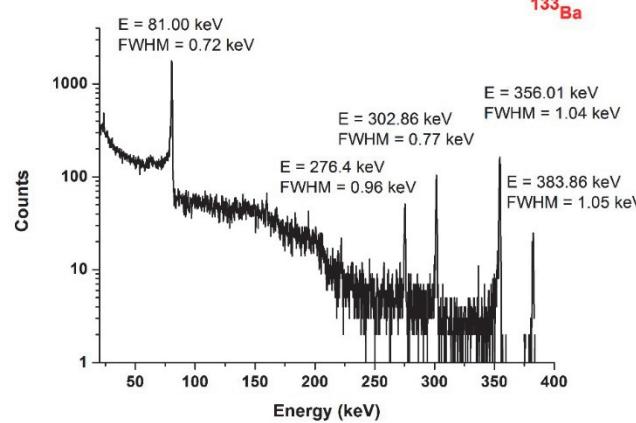
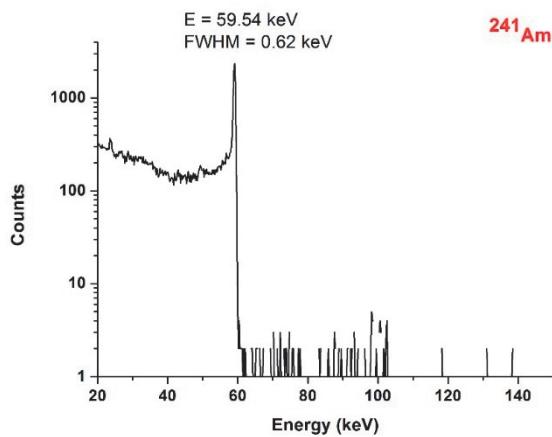
Sb
Ion Implantation
 $(6 \times 10^{15} \text{ Sb cm}^{-2}, 50 \text{ KeV, at LN}_2)$



(from E. Bruno et al., JAP (2010))

Test of small HPGe prototype: detector configuration

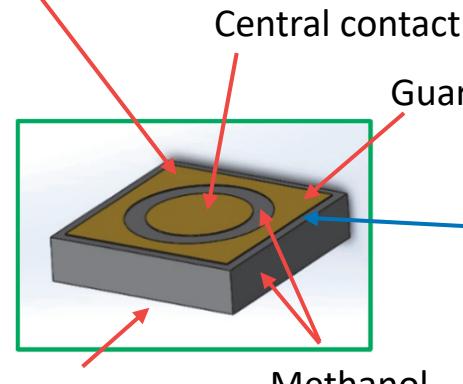
Sources: ^{241}Am , ^{152}Eu and ^{133}Ba



Good energy resolution all the energy range up to 400KeV

Prototype HPGe by LTA technology @LNL-INFN

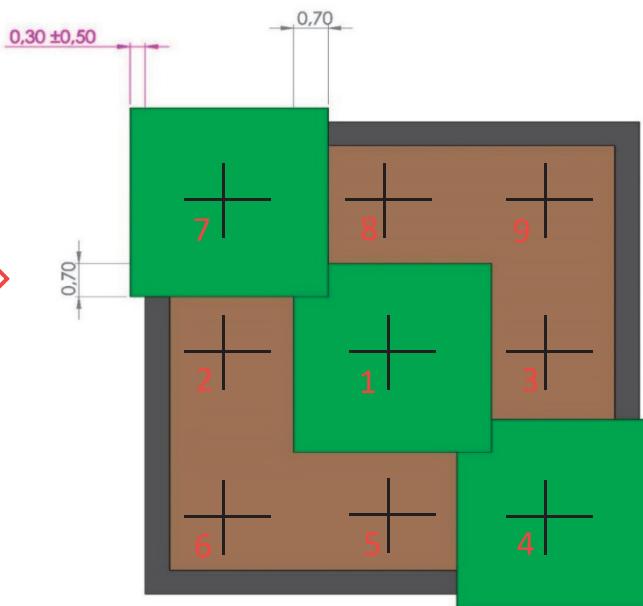
Deposition of gold
 $<100\text{nm}$



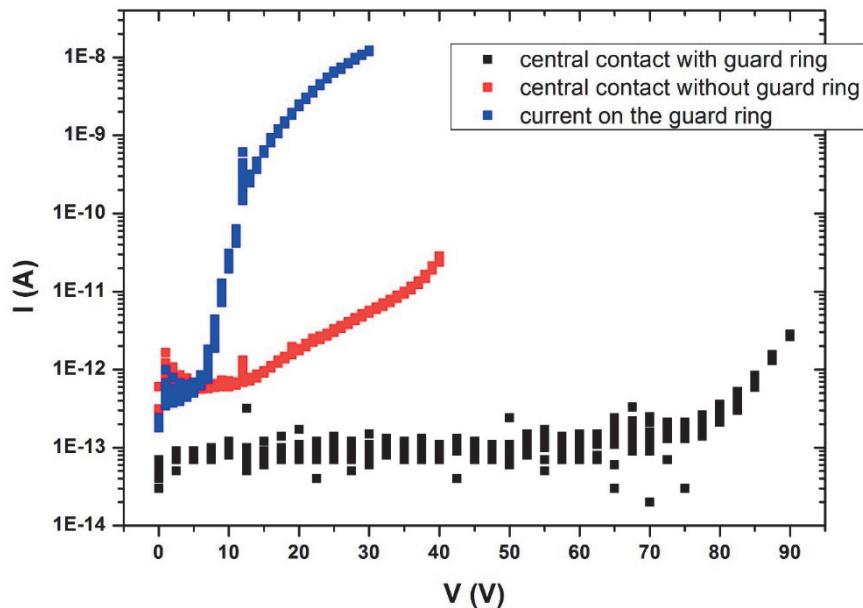
Sb deposition all
the surface
(10x10)mm²

Laser thermal annealing

with 9 laser spots (4x4)mm² all the Sb
surface (10x10)mm² was annealed

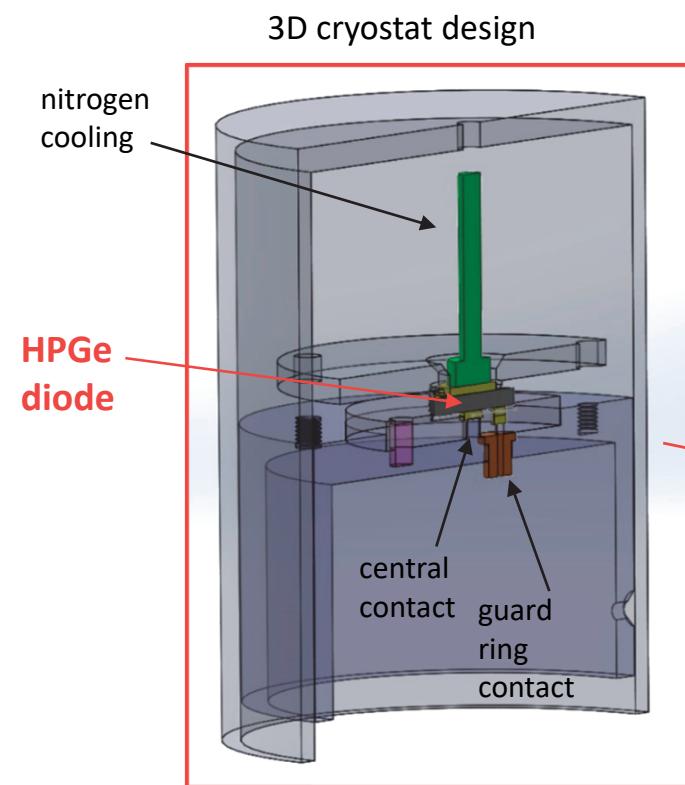


Test of small HPGe prototype: I-V diode configuration



Central contact low level of
leakeage current, $1pA$ @ $80V$

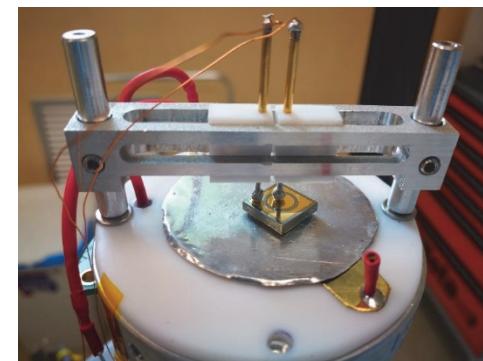
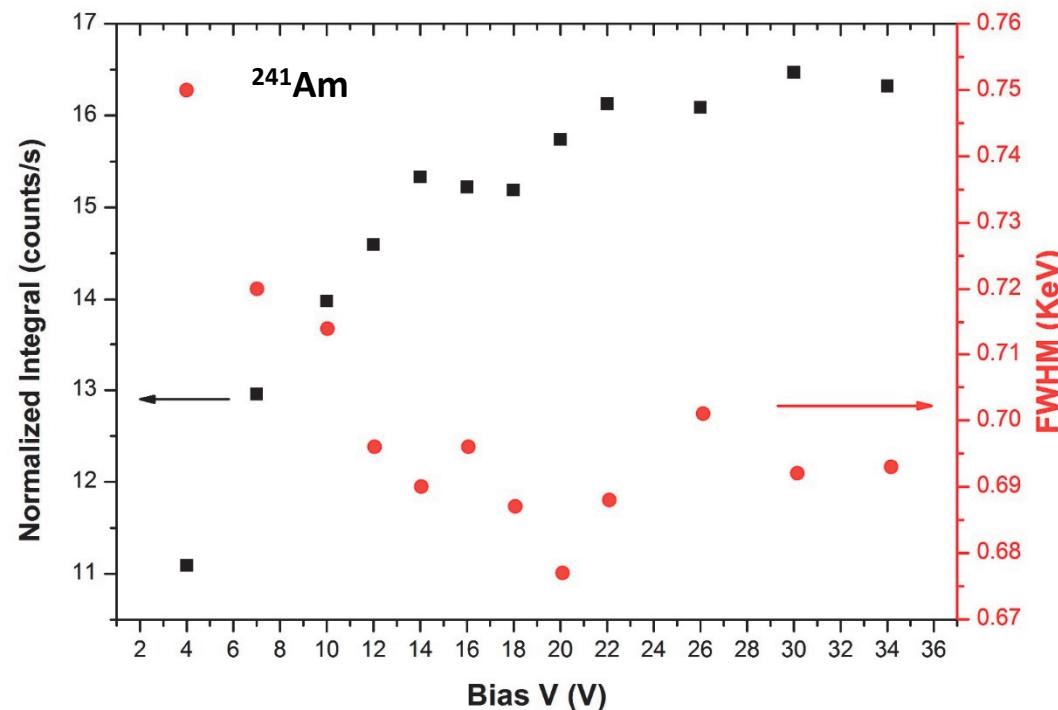
Direct bias $V=0.5$ V $I=0.8 \mu A$



W. Raniero (LNL - INFN) PSeGe 2018

Test of small HPGe prototype: detector configuration

Depletion Voltage - Energy resolution

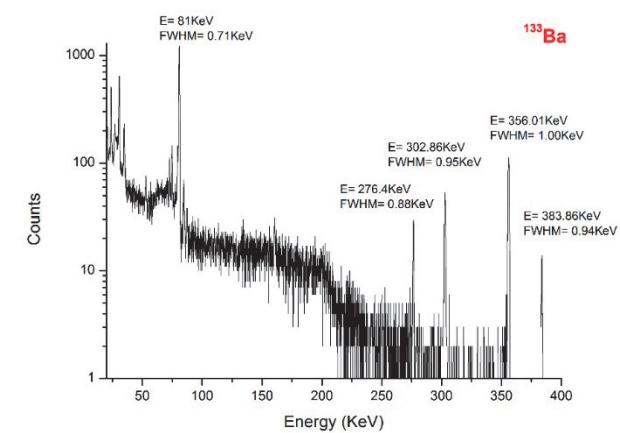
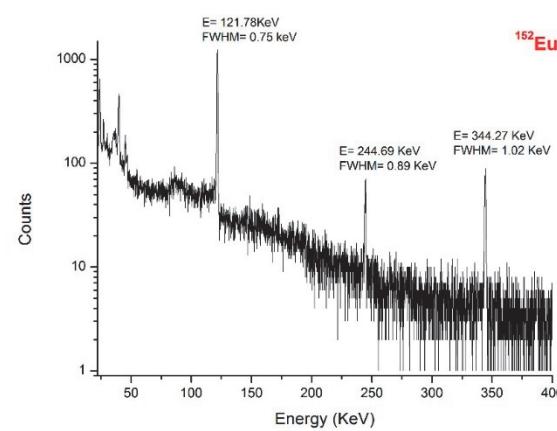
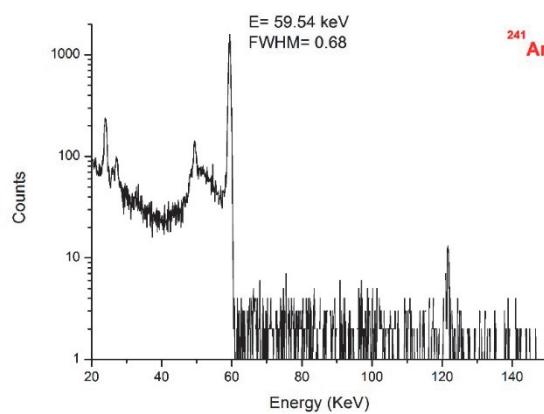


central contact
0.68 keV @ 59.54 keV (^{241}Am)

- detector fully depleted
(plateau of normalized integral)
- very good energy resolution

Test of small HPGe prototype: detector configuration

Sources: ^{241}Am , ^{152}Eu and ^{133}Ba



Good energy resolution all the energy range up to 400KeV

SUMMARY

Summary

- Several passivation routes have been applied to a planar HPGe detector and their effects on the detector characteristics have been investigated.
- Lateral scan measurements highlighted the electrical nature of the passivated surface (either n-type or p-type) and its influence with bulk properties of Ge dets.
- Hydride-based passivations are the bests to reduce dead layers in HPGe dets.
- A detector coating has been developed to substitute the mechanical encapsulation for protecting and stabilizing the passivated surfaces (also in between segments!)
- A new method to produce contacts based in laser annealing techniques is very promising. A novel Sb contact has been developed.

Work in progress

- Development of planar detectors with laser-annealed Sb contacts (scaling up)
- Development of detector samples with novel contacts using different deposition methods (vacuum evaporation, spin coating, etc.) and different doping elements (P, As for n contacts and B, Ga for p contacts).

